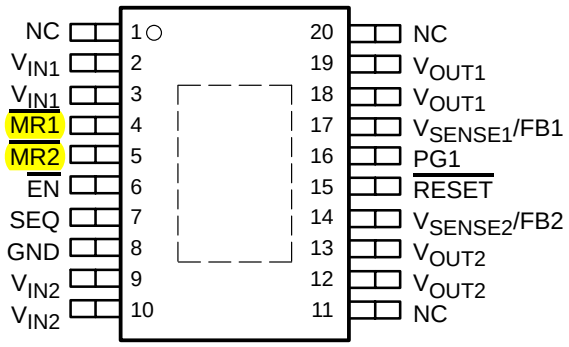
- Dual Output Voltages for Split-Supply Applications
- Selectable Power Up Sequencing for DSP Applications (See Part Number TPS702xx for Independently Enabled Outputs)
- Output Current Range of 500 mA on Regulator 1 and 250 mA on Regulator 2
- Fast Transient Response
- Voltage Options Are 3.3-V/2.5-V, 3.3-V/1.8-V, 3.3-V/1.5-V, 3.3-V/1.2-V, and Dual Adjustable Outputs
- Open Drain Power-On Reset With 120-ms Delay
- Open Drain Power Good for Regulator 1
- Ultralow 190 μA (typ) Quiescent Current
- 1-μA Input Current During Standby
- Low Noise: 65 μV_{RMS} Without Bypass Capacitor
- Quick Output Capacitor Discharge Feature
- Two Manual Reset Inputs
- 2% Accuracy Over Load and Temperature
- Undervoltage Lockout (UVLO) Feature
- 20-Pin PowerPAD™ TSSOP Package
- Thermal Shutdown Protection

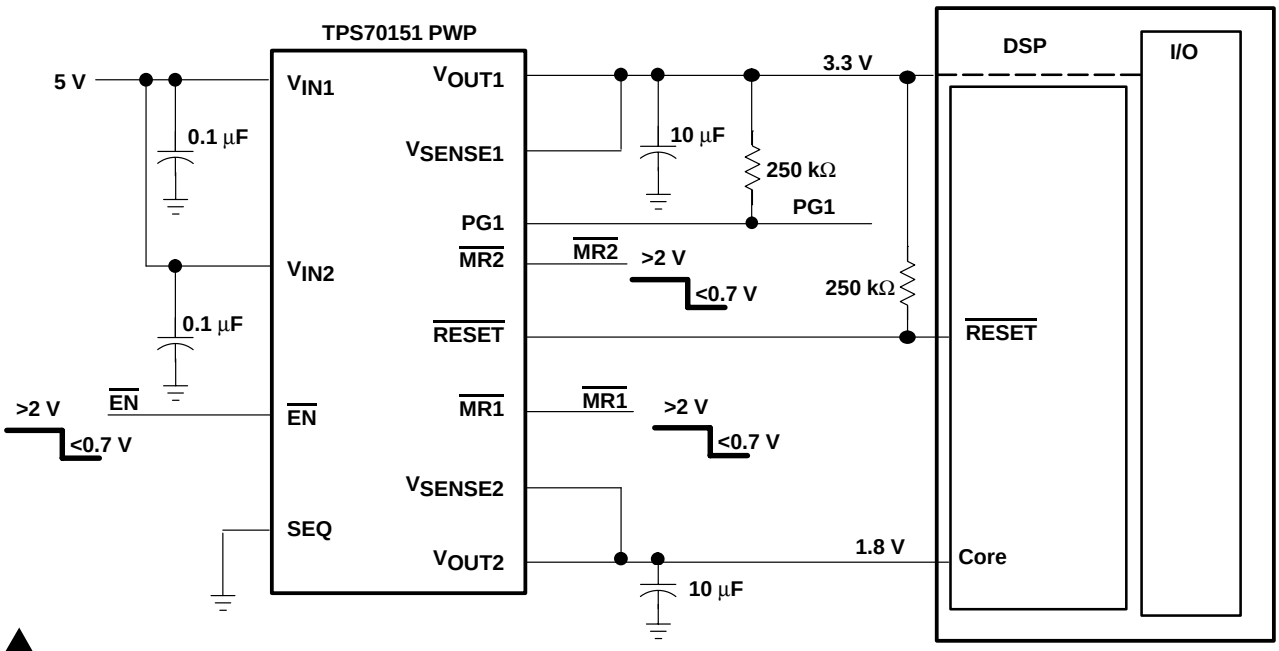
VOUT1输出电流为500mA. VOUT2输出

PWP PACKAGE
(TOP VIEW)



description

TPS701xx family devices are designed to provide a complete power management solution for the TMS320™ DSP family, processor power, ASIC, FPGA, and digital applications where dual output voltage regulators are required. Easy programmability of the sequencing function makes the TPS701xx family ideal for any TMS320 DSP applications with power sequencing requirement. Differentiated features, such as accuracy, fast transient response, SVS supervisory circuit, manual reset inputs, and enable function, provide a complete system solution.



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description (continued)

The TPS701xx family of voltage regulators offers very low dropout voltage and dual outputs with power-up sequence control, which is designed primarily for DSP applications. These devices have extremely low noise output performance without using any added filter bypass capacitors and are designed to have a fast transient response and be stable with 10 uF low ESR capacitors.

These devices have fixed 3.3-V/2.5-V, 3.3-V/1.8-V, 3.3-V/1.5-V, 3.3-V/1.2-V, and adjustable/adjustable voltage options. Regulator 1 can support up to 500 mA, and regulator 2 can support up to 250 mA. Separate voltage inputs allow the designer to configure the source power.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 170 mV on regulator 1) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (maximum of 230 µA over the full range of output current). This LDO family also features a sleep mode; applying a high signal to $\overline{EN}$ (enable) shuts down both regulators, reducing the input current to 1 µA at T_J = 25°C.

The device is enabled when the $\overline{EN}$ pin is connected to a low-level input voltage. The output voltages of the two regulators are sensed at the V_{SENSE1} and V_{SENSE2} pins respectively.

The input signal at the SEQ pin controls the power-up sequence of the two regulators. When the device is enabled and the SEQ terminal is pulled high or left open, V_{OUT2} turns on first and V_{OUT1} remains off until V_{OUT2} reaches approximately 83% of its regulated output voltage. At that time V_{OUT1} is turned on. If V_{OUT2} is pulled below 83% (i.e. over load condition) V_{OUT1} is turned off. Pulling the SEQ terminal low, reverses the power-up order and V_{OUT1} is turned on first. The SEQ pin is connected to an internal pullup current source.

For each regulator, there is an internal discharge transistor to discharge the output capacitor when the regulator is turned off(disabled).

The PG1 pin reports the voltage conditions at the V_{OUT1}, which can be used to implement a SVS for the circuitry supplied by regulator 1.

The TPS701xx features a $\overline{RESET}$ (SVS, POR, or Power On Reset). $\overline{RESET}$ output initiates a reset in DSP systems and related digital applications in the event of an undervoltage condition. $\overline{RESET}$ indicates the status of the V_{OUT2} and both manual reset pins ($\overline{MR1}$ and $\overline{MR2}$). When V_{OUT2} reaches 95% of its regulated voltage and $\overline{MR1}$ and $\overline{MR2}$ are in the logic high state, $\overline{RESET}$ goes to a high impedance state after 120 ms delay. $\overline{RESET}$ goes to logic low state when V_{OUT2} regulated output voltage is pulled below 95% (i.e. over load condition) of its regulated voltage. To monitor V_{OUT1}, the PG1 output pin can be connected to $\overline{MR1}$ or $\overline{MR2}$.

The device has an undervoltage lockout UVLO circuit which prevents the internal regulators from turning on until V_{IN1} reaches 2.5 V.

AVAILABLE OPTIONS

T_J	REGULATOR 1 V_O (V)	REGULATOR 2 V_O (V)	TSSOP (PWP)
–40°C to 125°C	3.3 V	1.2 V	TPS70145PWP
	3.3 V	1.5 V	TPS70148PWP
	3.3 V	1.8 V	TPS70151PWP
	3.3 V	2.5 V	TPS70158PWP
	Adjustable (1.22 V to 5.5 V)	Adjustable (1.22 V to 5.5 V)	TPS70102PWP

NOTE: The TPS70102 is programmable using external resistor dividers (see application information) The PWP package is available taped and reeled. Add an R suffix to the device type (e.g., TPS70102PWPR).

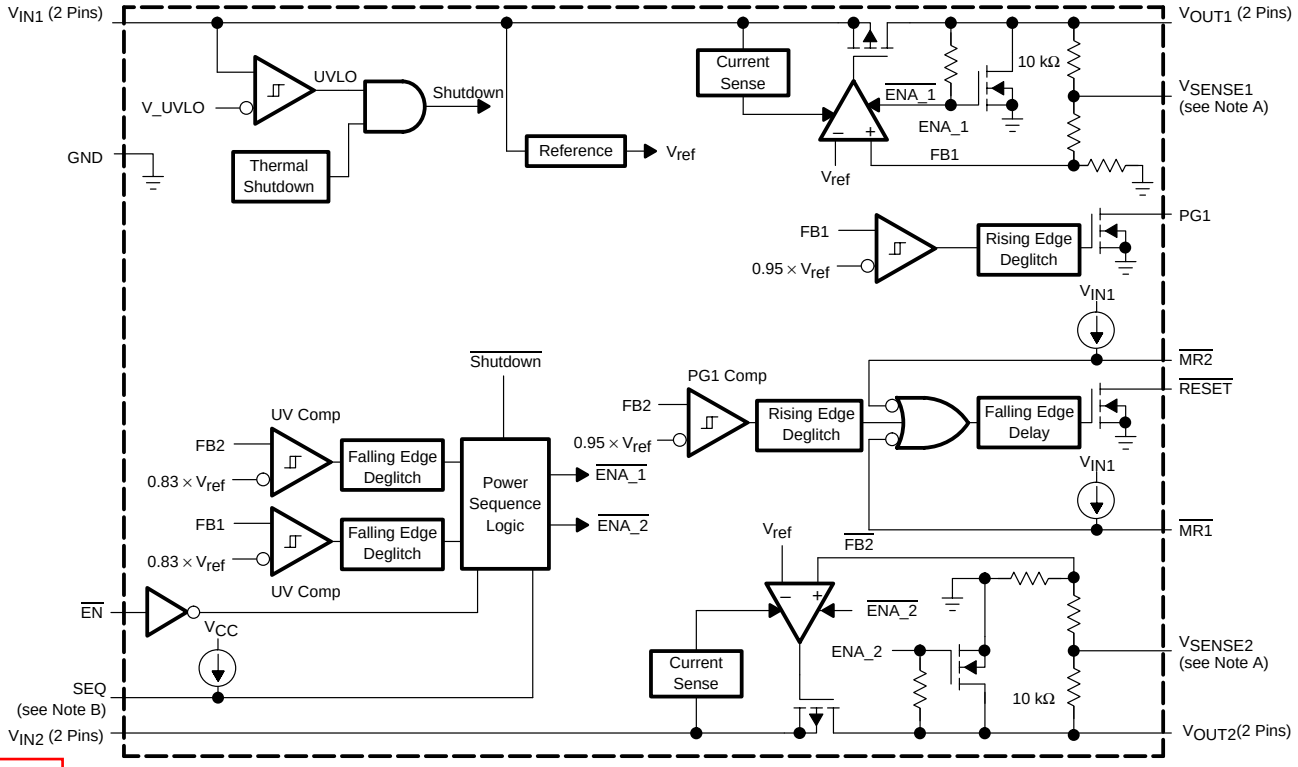
SEQ控制上电顺序。2812先上3.3V 再上1.8V

EN 用于使能输出通道。高电平时，关断2个输出。

复位受控于VOUT2的状态和手动复位引脚MR1和MR2的状态。

监视VOUT1的方法

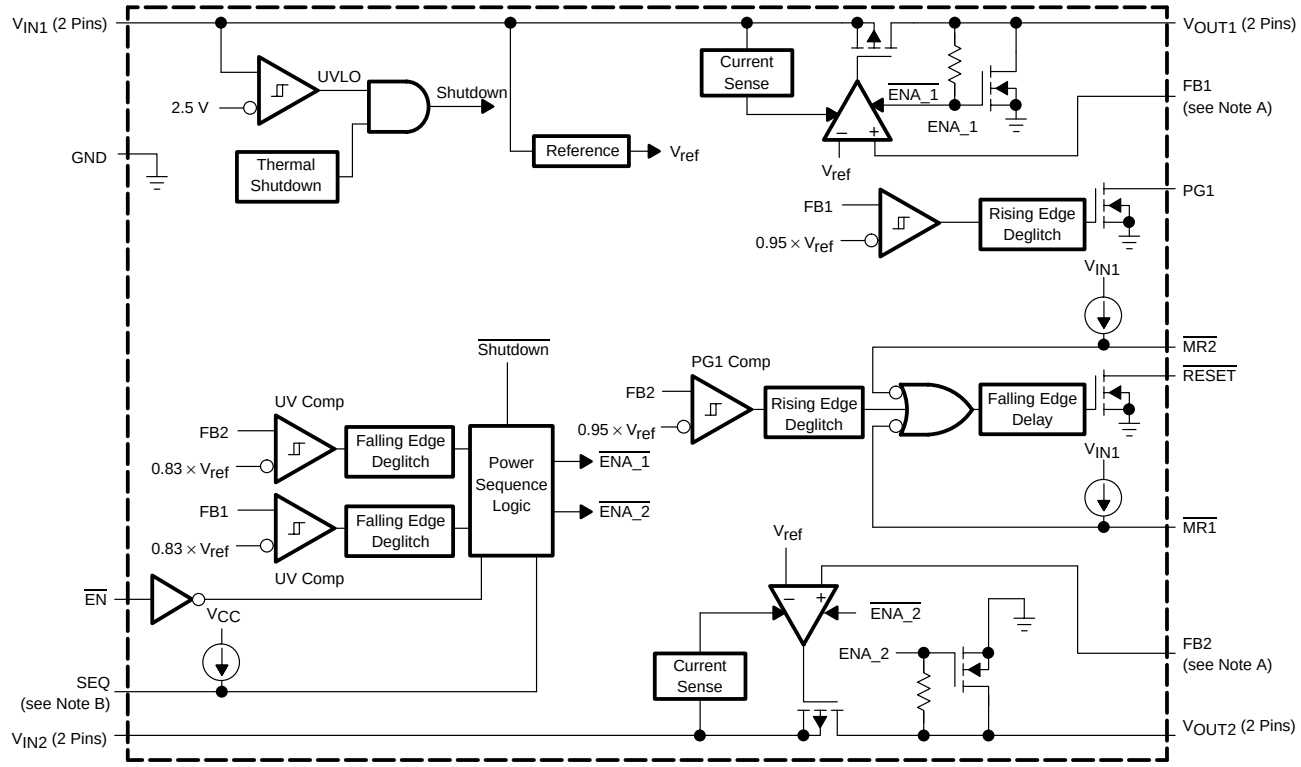
detailed block diagram – fixed voltage version



NOTES: A. For most applications, V_{SENSE1} and V_{SENSE2} should be externally connected to V_{OUT} as close as possible to the device. For other implementations, refer to SENSE terminal connection discussion in the application information section.

B. If the SEQ terminal is floating at the input, the V_{OUT2} powers up first.

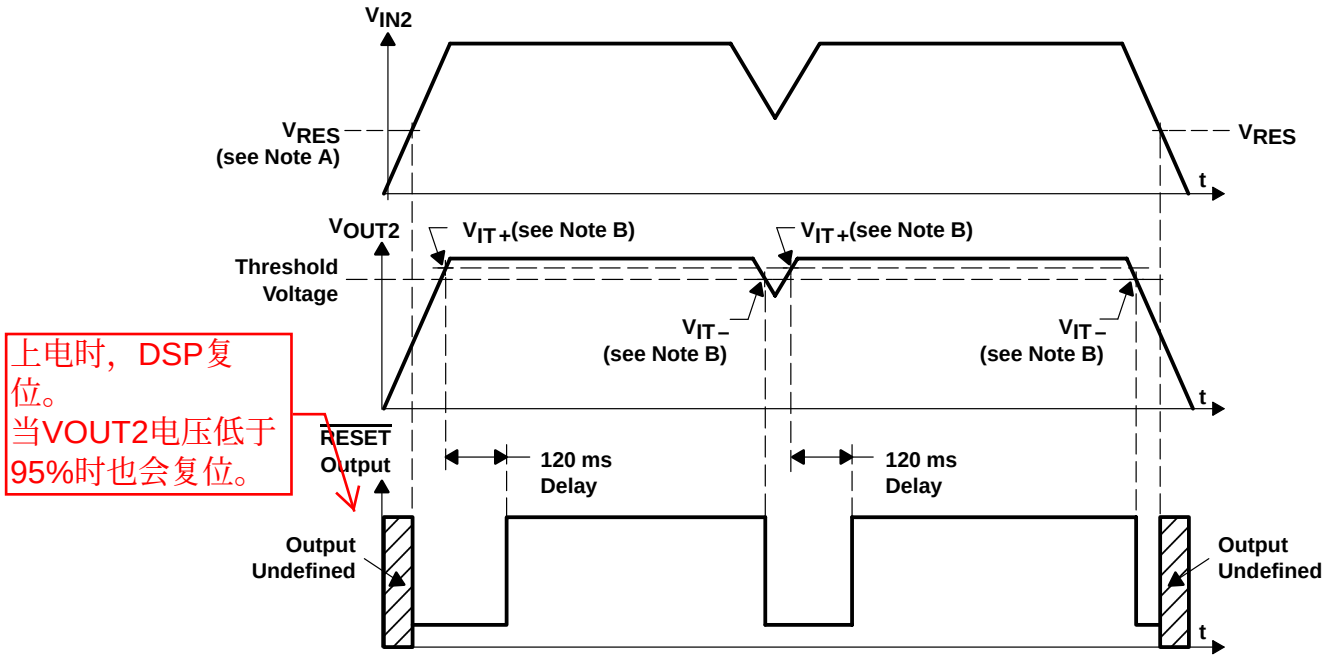
detailed block diagram – adjustable voltage version



NOTES: A. For most applications, FB1 and FB2 should be externally connected to resistor dividers as close as possible to the device. For other implementations, refer to FB terminals connection discussion in the application information section.

B. If the SEQ terminal is floating at the input, the V_{OUT2} powers up first.

$\overline{\text{RESET}}$ timing diagram (with V_{IN1} powered up)

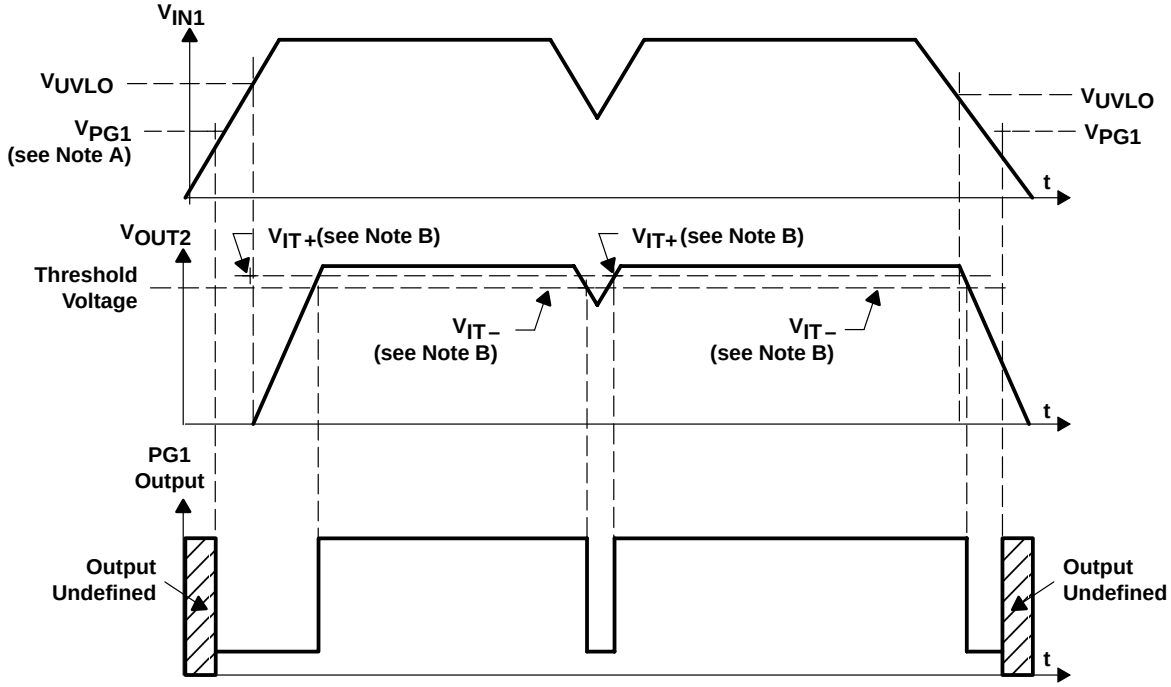


上电时，DSP复位。
当VOUT2电压低于95%时也会复位。

NOTES: A. V_{RES} is the minimum input voltage for a valid $\overline{\text{RESET}}$. The symbol V_{RES} is not currently listed within EIA or JEDEC standards for semiconductor symbology.

B. V_{IT} –Trip voltage is typically 5% lower than the output voltage (95%V_O) V_{IT-} to V_{IT+} is the hysteresis voltage.

PG1 timing diagram



NOTES: A. V_{PG1} is the minimum input voltage for a valid PG1. The symbol V_{PG1} is not currently listed within EIA or JEDEC standards for semiconductor symbology.

B. V_{IT} –Trip voltage is typically 5% lower than the output voltage (95%V_O) V_{IT-} to V_{IT+} is the hysteresis voltage.

Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
$\overline{EN}$	6	I	Active low enable
GND	8		Ground
$\overline{MR1}$	4	I	Manual reset input 1, active low, pulled up internally
$\overline{MR2}$	5	I	Manual reset input 2, active low, pulled up internally
NC	1, 11, 20		No connection
PG1	16	O	Open drain output, low when V_{OUT1} voltage is less than 95% of the nominal regulated voltage
$\overline{RESET}$	15	O	Open drain output, SVS (power on reset) signal, active low
SEQ	7	I	Power up sequence control: SEQ=High, V_{OUT2} powers up first; SEQ=Low, V_{OUT1} powers up first, SEQ terminal pulled up internally.
V_{IN1}	2, 3	I	Input voltage of regulator 1
V_{IN2}	9, 10	I	Input voltage of regulator 2
V_{OUT1}	18, 19	O	Output voltage of regulator 1
V_{OUT2}	12, 13	O	Output voltage of regulator 2
V_{SENSE2}/FB2	14	I	Regulator 2 output voltage sense/ regulator 2 feedback for adjustable
V_{SENSE1}/FB1	17	I	Regulator 1 output voltage sense/ regulator 1 feedback for adjustable

detailed description

The TPS701xx low dropout regulator family provides dual regulated output voltages for DSP applications, which require high performance power management solution. These devices provide fast transient response and high accuracy with small output capacitors, while drawing low quiescent current. Programmable sequencing provides a power solution for DSPs without any external component requirements. This reduces the component cost and board space while increasing total system reliability. TPS701xx family has an enable feature which puts the device in sleep mode reducing the input currents to less than 3 μA. Other features are integrated SVS (Power On Reset, $\overline{RESET}$) and Power Good (PG1) that monitor output voltages and provide logic output to the system. These differentiated features provide a complete DSP power solution.

The TPS701xx, unlike many other LDOs, feature very low quiescent current which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). The TPS701xx uses a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and stable over the full load range.

pin functions

enable

The $\overline{EN}$ terminal is an input which enables or shuts down the device. If $\overline{EN}$ is at a voltage high signal, the device is in shutdown mode. When the $\overline{EN}$ goes to voltage low, the device is enabled.

sequence

The SEQ terminal is an input that programs which output voltage (V_{OUT1} or V_{OUT2}) is turned on first. When the device is enabled and the SEQ terminal is pulled high or left open, V_{OUT2} turns on first and V_{OUT1} remains off until V_{OUT2} reaches approximately 83% of its regulated output voltage. At that time the V_{OUT1} is turned on. If V_{OUT2} is pulled below 83% (i.e., over load condition) V_{OUT1} is turned off. These terminals have a 6-μA pullup current to V_{IN1}.

Pulling the SEQ terminal low reverses the power-up order and V_{OUT1} is turned on first. For detail timing diagrams refer to Figures 36 through 42.

power-good

The PG1 is an open drain, active high output terminal which indicates the status of the V_{OUT1} regulator. When the V_{OUT1} reaches 95% of its regulated voltage, PG1 will go to a high impedance state. It will go to a low impedance state when it is pulled below 95% (i.e. over load condition) of its regulated voltage. The open drain output of the PG1 terminal requires a pullup resistor.

manual reset pins ($\overline{MR1}$ and $\overline{MR2}$)

$\overline{MR1}$ and $\overline{MR2}$ are active low input terminals used to trigger a reset condition. When either $\overline{MR1}$ or $\overline{MR2}$ is pulled to logic low, a POR ($\overline{RESET}$) will occur. These terminals have a 6-µA pullup current to V_{IN1}.

sense (V_{SENSE1}, V_{SENSE2})

The sense terminals of fixed-output options must be connected to the regulator output, and the connection should be as short as possible. Internally, sense connects to high-impedance wide-bandwidth amplifiers through a resistor-divider network and noise pickup feeds through to the regulator output. It is essential to route the sense connection in such a way to minimize/avoid noise pickup. Adding RC networks between the V_{SENSE} terminals and V_{OUT} terminals to filter noise is not recommended because it can cause the regulators to oscillate.

FB1 and FB2 和外部电阻电路相连接，用于反馈

FB1 and FB2 are input terminals used for adjustable-output devices and must be connected to the external feedback resistor divider. FB1 and FB2 connections should be as short as possible. It is essential to route them in such a way as to minimize/avoid noise pickup. Adding RC networks between the FB terminals and V_{OUT} terminals to filter noise is not recommended because it can cause the regulators to oscillate.

$\overline{RESET}$ indicator

The TPS701xx features a $\overline{RESET}$ ($\overline{SVS}$, POR, or Power On Reset). $\overline{RESET}$ can be used to drive power-on reset circuitry or a low-battery indicator. $\overline{RESET}$ is an active low, open drain output which indicates the status of the V_{OUT2} regulator and both manual reset pins ($\overline{MR1}$ and $\overline{MR2}$). When V_{OUT2} exceeds to 95% of its regulated voltage, and $\overline{MR1}$ and $\overline{MR2}$ are in the high impedance state, $\overline{RESET}$ will go to a high-impedance state after 120-ms delay. $\overline{RESET}$ will go to a low impedance state when V_{OUT2} is pulled below 95% (i.e. over load condition) of its regulated voltage. To monitor V_{OUT1} , PG1 output pin can be connected to $\overline{MR1}$ or $\overline{MR2}$. The open drain output of the $\overline{RESET}$ terminal requires a pullup resistor. If $\overline{RESET}$ is not used, it can be left floating.

V_{IN1} and V_{IN2}

V_{IN1} and V_{IN2} are input to the regulators. Internal bias voltages are powered by V_{IN1}.

V_{OUT1} and V_{OUT2}

V_{OUT1} and V_{OUT2} are output terminals of the LDO.

absolute maximum ratings over operating junction temperature (unless otherwise noted)†

Input voltage range‡: V_{IN1}	–0.3 V to 7 V
V_{IN2}	–0.3 V to 7 V
Voltage range at $\overline{EN}$	–0.3 V to 7 V
Output voltage range (V_{OUT1}, V_{SENSE1})	5.5 V
Output voltage range (V_{OUT2}, V_{SENSE2})	5.5 V
Maximum $\overline{RESET}$, PG1 voltage	7 V
Maximum $\overline{MR1}$, $\overline{MR2}$, and SEQ voltage	V_{IN1}
Peak output current	Internally limited
Continuous total power dissipation	See Dissipation Rating Tables
Operating virtual junction temperature range, T_J	–40°C to 150°C
Storage temperature range, T_{stg}	–65°C to 150°C
ESD rating, HBM	2 kV

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
‡ All voltages are tied to network ground.

DISSIPATION RATING TABLE

PACKAGE	AIR FLOW (CFM)	$T_A \le 25°C$	DERATING FACTOR	$T_A = 70°C$	$T_A = 85°C$
PWP§	0	3.067 W	30.67 mW/°C	1.687 W	1.227 W
	250	4.115 W	41.15 mW/°C	2.265 W	1.646 W

§ This parameter is measured with the recommended copper heat sink pattern on a 4-layer PCB, 1 oz. copper on 4-in × 4-in ground layer. For more information, refer to TI technical brief SLMA002.

recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V_I†	2.7	6	V
Output current, I_O (regulator 1)	0	500	mA
Output current, I_O (regulator 2)	0	250	mA
Output voltage range (for adjustable option)	1.22	5.5	V
Operating virtual junction temperature, T_J	–40	125	°C

† To calculate the minimum input voltage for maximum output current, use the following equation: $V_{I(min)} = V_{O(max)} + V_{DO(max\ load)}$.

electrical characteristics over recommended operating junction temperature (T_J = –40°C to 125°C) V_{IN1} or V_{IN2} = $V_{O(nom)}$ + 1 V, I_O = 1 mA, $\overline{EN}$ = 0, C_O = 33 µF (unless otherwise noted)

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_O	Output voltage (see Notes 1 and 3)	Reference voltage	2.7 V < V_I < 6 V, T_J = 25°C	FB connected to V_O		1.22		V
			2.7 V < V_I < 6 V,	FB connected to V_O	0.96		1.244	
		1.2 V Output	2.7 V < V_I < 6 V,	T_J = 25°C		1.2		
			2.7 V < V_I < 6 V		1.176		1.224	
		1.5 V Output	2.7 V < V_I < 6 V,	T_J = 25°C		1.5		
			2.7 V < V_I < 6 V		1.47		1.53	
		1.8 V Output	2.8 V < V_I < 6 V,	T_J = 25°C		1.8		
			2.8 V < V_I < 6 V		1.764		1.836	
		2.5 V Output	3.5 V < V_I < 6 V,	T_J = 25°C		2.5		
			3.5 V < V_I < 6 V		2.45		2.55	
		3.3 V Output	4.3 V < V_I < 6 V,	T_J = 25°C		3.3		V
			4.3 V < V_I < 6 V		3.234		3.366	
Quiescent current (GND current) for regulator 1 and regulator 2, $\overline{EN}$ = 0 V, (see Note 1)			See Note 3,	T_J = 25°C		190		µA
			See Note 3				230	
Output voltage line regulation ($\Delta V_O/V_O$) for regulator 1 and regulator 2 (see Note 2)			V_O + 1 V < V_I ≤ 6 V,	T_J = 25°C, See Note 1		0.01%		V
			V_O + 1 V < V_I ≤ 6 V,	See Note 1			0.1%	
Load regulation for V_{OUT1} and V_{OUT2}			T_J = 25°C,	See Note 3		1		mV
V_n	Output noise voltage	Regulator 1	BW = 300 Hz to 50 kHz,	C_O = 33 µF, T_J = 25°C		65		µVrms
		Regulator 2				65		
Output current limit		Regulator 1	V_O = 0 V			1.6	1.9	A
		Regulator 2				0.750	1	
Thermal shutdown junction temperature						150		°C
$I_{I(standby)}$	Standby current	Regulator 1	$\overline{EN}$ = V_I,	T_J = 25°C			1	µA
			$\overline{EN}$ = V_I				3	
		Regulator 2	$\overline{EN}$ = V_I,	T_J = 25°C			1	µA
			$\overline{EN}$ = V_I				3	
PSRR	Power supply ripple rejection		f = 1 kHz, C_O = 33 µF,	T_J = 25°C, See Note 1		60		dB

NOTES: 1. Minimum input operating voltage is 2.7 V or $V_{O(typ)}$ + 1 V, whichever is greater. Maximum input voltage = 6 V, minimum output current = 1 mA.

2. If V_O < 1.8 V then V_{Imax} = 6 V, V_{Imin} = 2.7 V:

$$\text{Line Regulation (mV)} = (\%/V) \times \frac{V_O\left(V_{Imax} - 2.7\ V\right)}{100} \times 1000$$

If V_O > 2.5 V then V_{Imax} = 6 V, V_{Imin} = Vo + 1 V:

$$\text{Line Regulation (mV)} = (\%/V) \times \frac{V_O\left(V_{Imax} - \left(V_O + 1\right)\right)}{100} \times 1000$$

3. I_O = 1 mA to 500 mA for Regulator 1 and 1 mA to 250 mA for Regulator 2.

electrical characteristics over recommended operating junction temperature (T_J = –40°C to 125°C) V_{IN1} or V_{IN2} = $V_{O(nom)}$ + 1 V, I_O = 1 mA, $\overline{EN}$ = 0, C_O = 33 µF (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
RESET terminal					
Minimum input voltage for valid $\overline{RESET}$	$I_{(RESET)}$ = 300 µA, $V_{(RESET)} \le$ 0.8 V		1.0	1.3	V
Trip threshold voltage	V_O decreasing	92%	95%	98%	V_O
Hysteresis voltage	Measured at V_O		0.5%		V_O
$t_{(\overline{RESET})}$	$\overline{RESET}$ pulse duration	80	120	160	ms
$t_{r(\overline{RESET})}$	Rising edge deglitch		30		µs
Output low voltage	V_I = 3.5 V, $I_{O(RESET)}$ = 1 mA		0.15	0.4	V
Leakage current	$V_{(RESET)}$ = 6 V			1	µA
PG1 terminal					
Minimum input voltage for valid PG1	$I_{(PG1)}$ = 300 µA, $V_{(PG1)} \le$ 0.8 V		1.0	1.3	V
Trip threshold voltage	V_O decreasing	92%	95%	98%	V_O
Hysteresis voltage	Measured at V_O		0.5%		V_O
$t_{r(PG1)}$	Rising edge deglitch		30		µs
Output low voltage	V_I = 2.7 V, $I_{O(PG1)}$ = 1 mA		0.15	0.4	V
Leakage current	$V_{(PG1)}$ = 6 V			1	µA
EN terminal					
High level $\overline{EN}$ input voltage		2			V
Low level $\overline{EN}$ input voltage				0.7	V
Input current ($\overline{EN}$)		–1		1	µA
Falling edge deglitch	Measured at V_O		140		µs
SEQ terminal					
High level SEQ input voltage		2			V
Low level SEQ input voltage				0.7	V
Falling edge deglitch	Measured at V_O		140		µs
SEQ pullup current source			6		µA
MR1 / MR2 terminals					
High level input voltage		2			V
Low level input voltage				0.7	V
Falling edge deglitch	Measured at V_O		140		µs
Pull up current source			6		µA
V_{OUT2} terminal					
V_{OUT2} UV comparator – positive-going input threshold voltage of V_{OUT1} UV comparator		80% V_O	83% V_O	86% V_O	V
V_{OUT2} UV comparator – hysteresis			0.5% V_O		mV
V_{OUT2} UV comparator – falling edge deglitch	V_{SENSE_2} decreasing below threshold		140		µs
Peak output current	2 ms pulse width		375		mA
Discharge transistor current	V_{OUT2} = 1.5 V		7.5		mA

electrical characteristics over recommended operating junction temperature (T_J = –40°C to 125°C) V_{IN1} or V_{IN2} = $V_{O(nom)}$ + 1 V, I_O = 1 mA, $\overline{EN}$ = 0, C_O = 33 μF (unless otherwise noted) (continued)

V_{OUT1} terminal					
V_{OUT1} UV comparator – positive-going input threshold voltage of V_{OUT1} UV comparator		80% V_O	83% V_O	86% V_O	V
V_{OUT1} UV comparator – hysteresis			0.5% V_O		mV
V_{OUT1} UV comparator – falling edge deglitch	V_{SENSE_1} decreasing below threshold		140		μs
Dropout voltage (see Note 4)	I_O = 500 mA, V_{IN1} = 3.2 V, T_J = 25°C		170		mV
Dropout voltage (see Note 4)	I_O = 500 mA, V_{IN1} = 3.2 V			275	mV
Peak output current	2 ms pulse width		750		mA
Discharge transistor current	V_{OUT1} = 1.5 V		7.5		mA
UVLO threshold		2.4		2.65	V
FB terminal					
Input current – TPS70102	FB = 1.8 V		1		μA

NOTE 4: Input voltage(V_{IN1} or V_{IN2}) = V_O(Typ) – 100 mV. 1.5-V, 1.8-V and 2.5-V regulators, the dropout voltage is limited by input voltage range. The 3.3 V regulator input voltage is set to 3.2 V to perform this test.

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
V_O	Output voltage	vs Output current	1 – 3
		vs Temperature	4 – 7
	Ground current	vs Junction temperature	8
PSRR	Power supply rejection ratio	vs Frequency	9 – 12
	Output spectral noise density	vs Frequency	13 – 16
Z_O	Output impedance	vs Frequency	17 – 20
	Dropout voltage	vs Temperature	21, 22
		vs Input voltage	23, 24
	Load transient response		25, 26
	Line transient response		27, 28
V_O	Output voltage and enable voltage	vs Time (start-up)	29, 30
	Equivalent series resistance	vs Output current	32 – 35

输出电压和输出电流的关系。

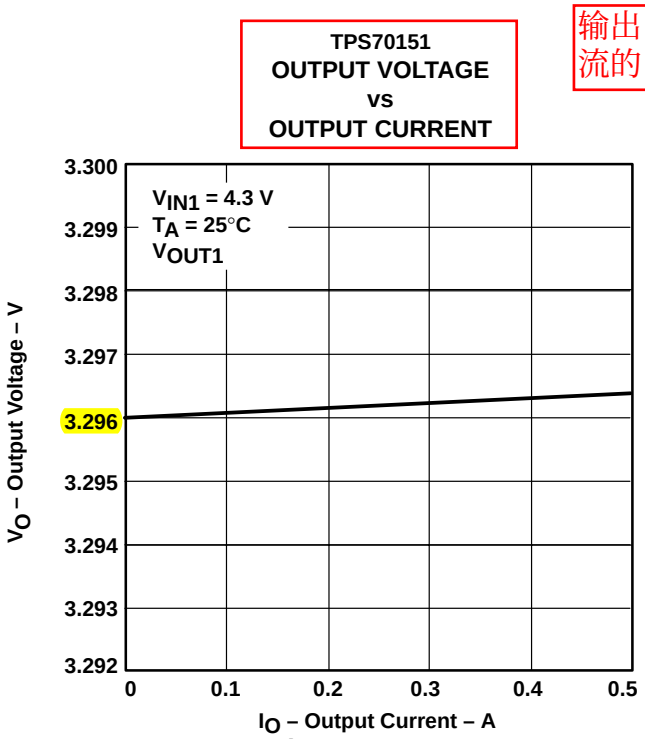


Figure 1

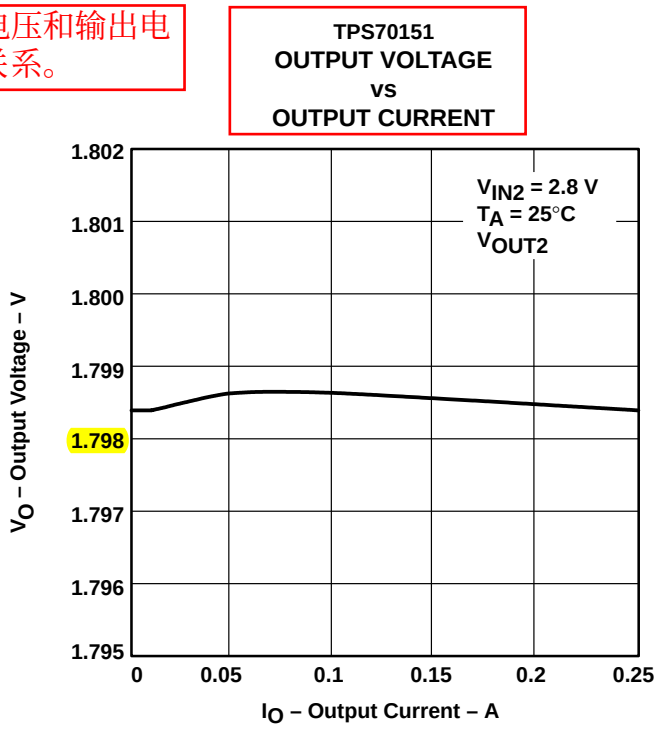


Figure 2

TYPICAL CHARACTERISTICS

TPS70145
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

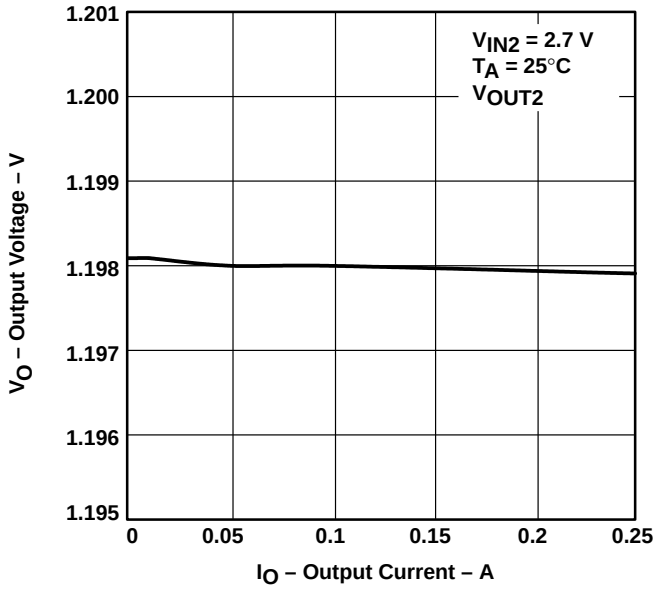


Figure 3

TPS70151
OUTPUT VOLTAGE
vs
TEMPERATURE

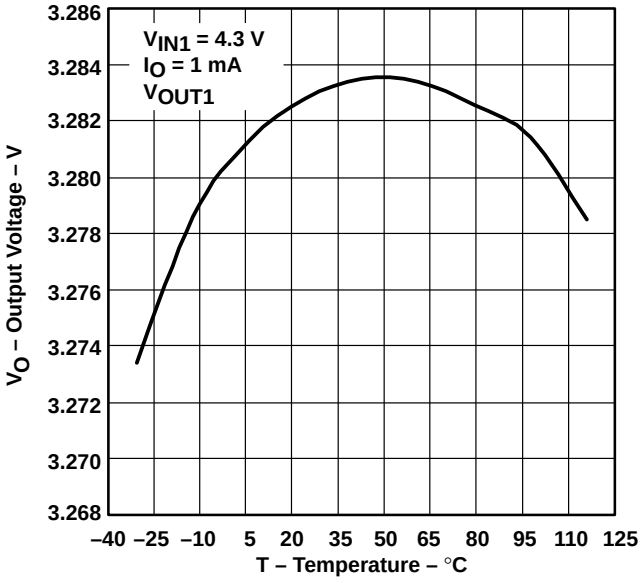


Figure 4

TPS70151
OUTPUT VOLTAGE
vs
TEMPERATURE

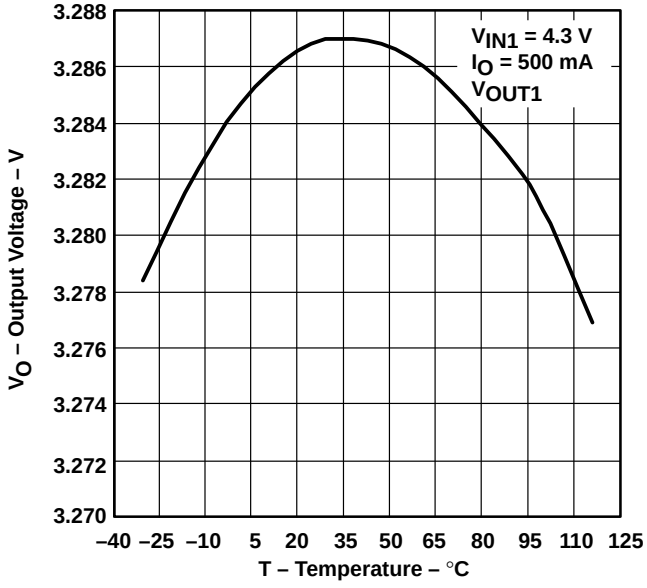


Figure 5

TYPICAL CHARACTERISTICS

TPS70151
OUTPUT VOLTAGE
vs
TEMPERATURE

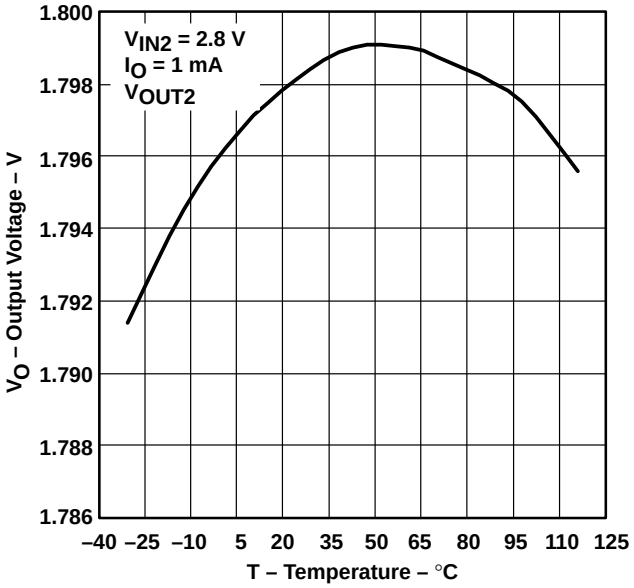


Figure 6

TPS70151
OUTPUT VOLTAGE
vs
TEMPERATURE

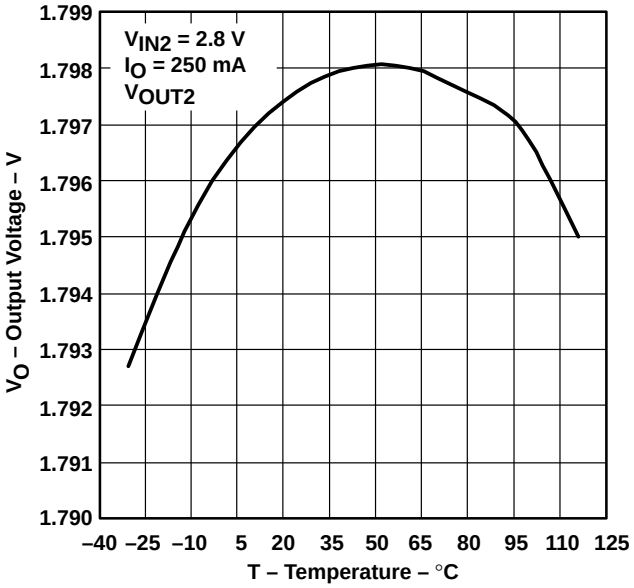


Figure 7

GROUND CURRENT
vs
JUNCTION TEMPERATURE

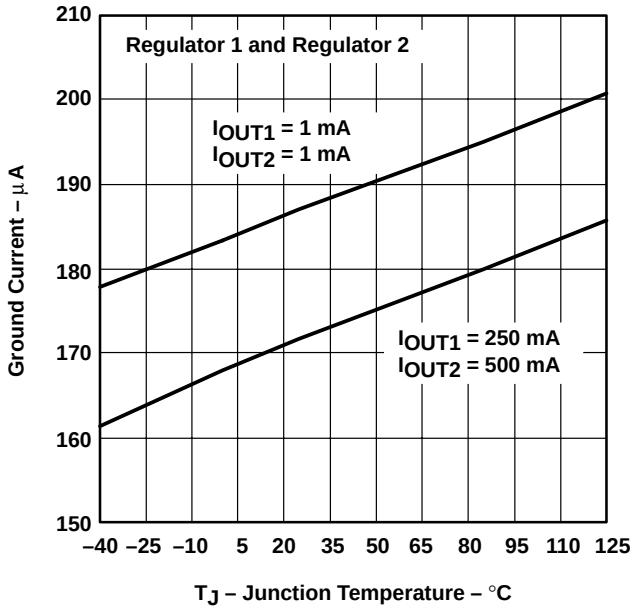


Figure 8

TYPICAL CHARACTERISTICS

TPS70151
POWER SUPPLY REJECTION RATIO
vs
FREQUENCY

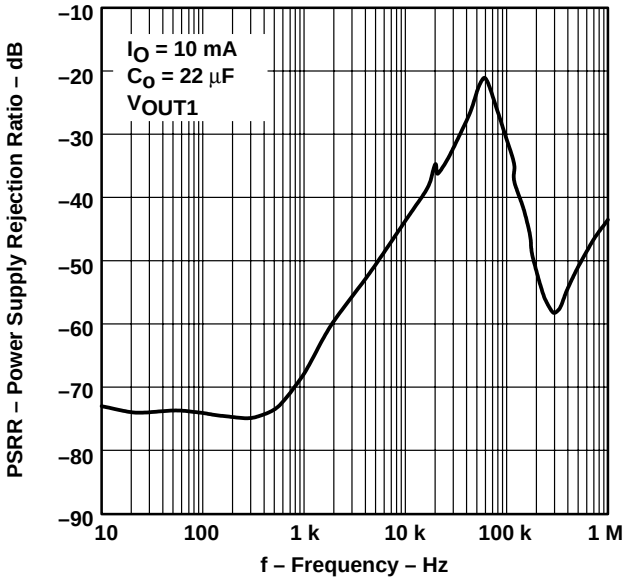


Figure 9

TPS70151
POWER SUPPLY REJECTION RATIO
vs
FREQUENCY

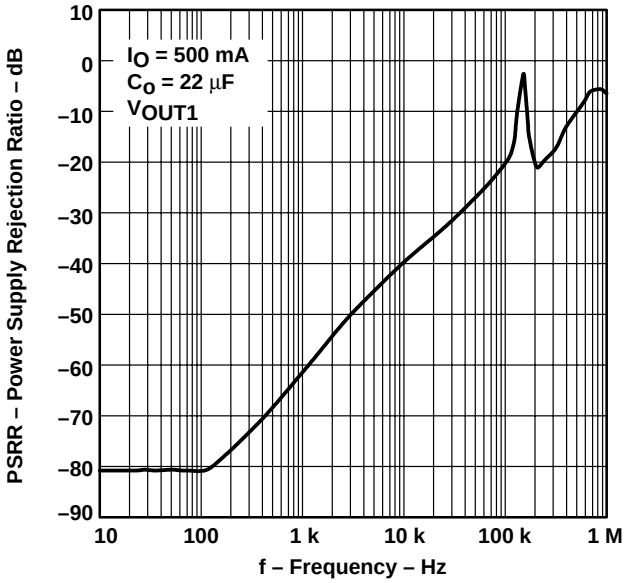


Figure 10

TPS70151
POWER SUPPLY REJECTION RATIO
vs
FREQUENCY

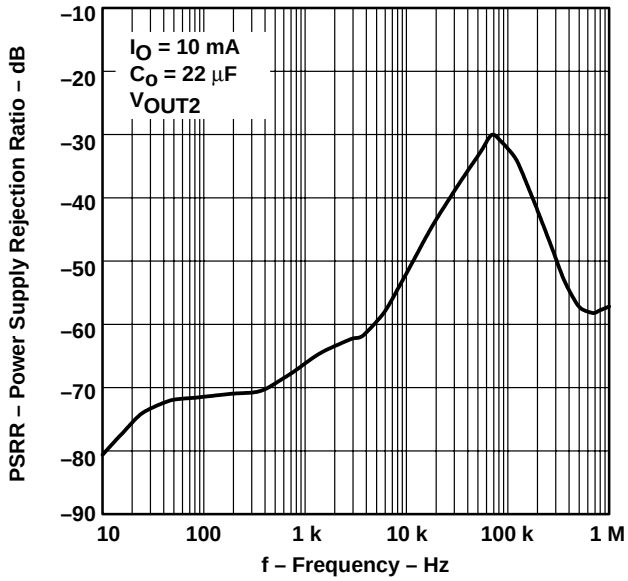


Figure 11

TPS70151
POWER SUPPLY REJECTION RATIO
vs
FREQUENCY

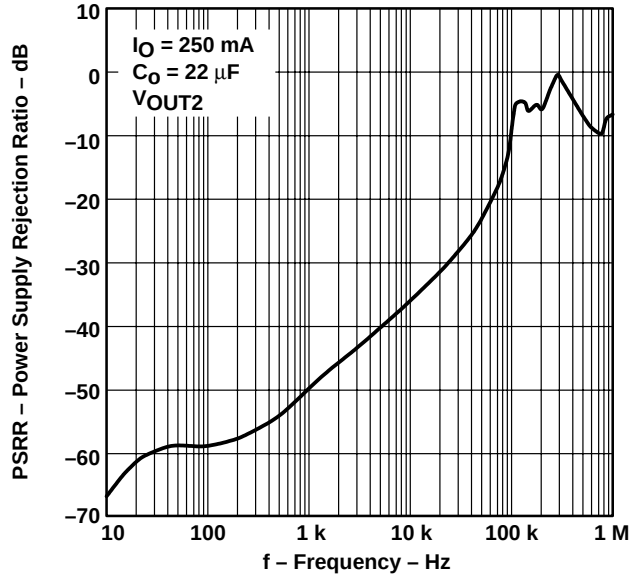


Figure 12

TYPICAL CHARACTERISTICS

OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

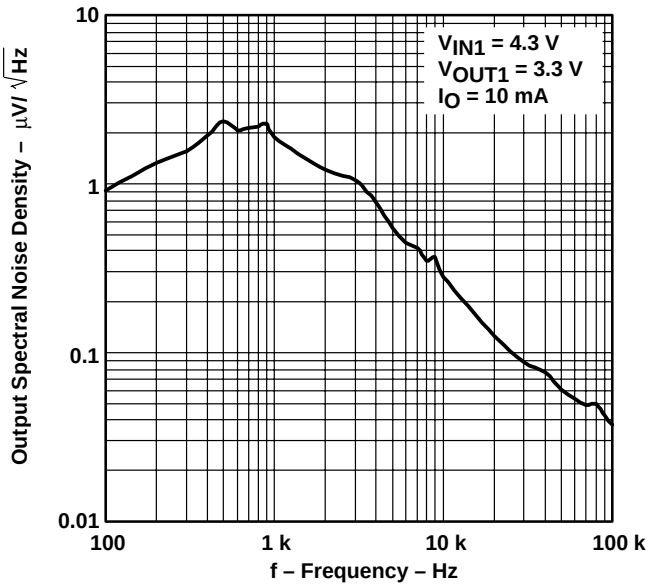


Figure 13

OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

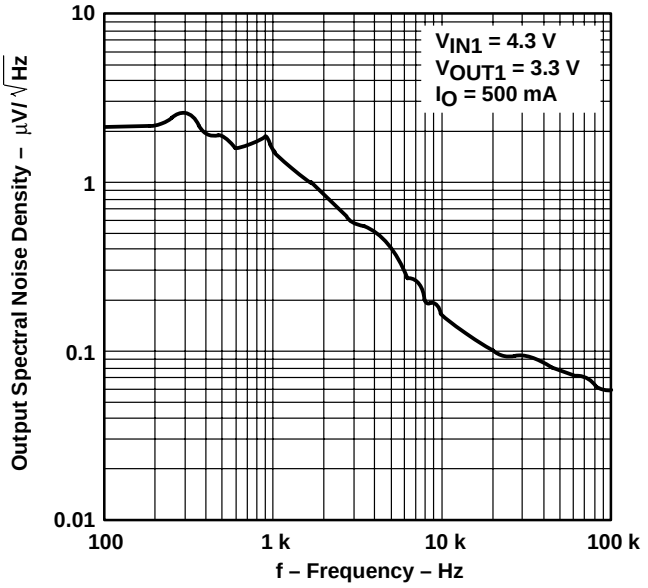


Figure 14

OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

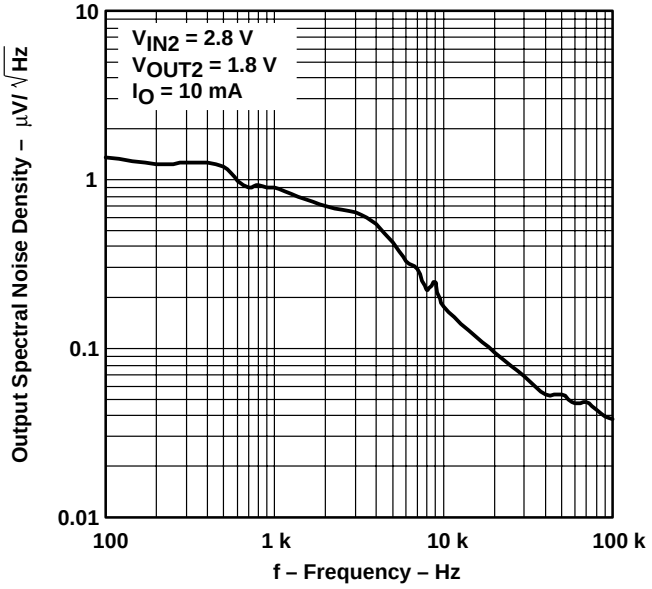


Figure 15

OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

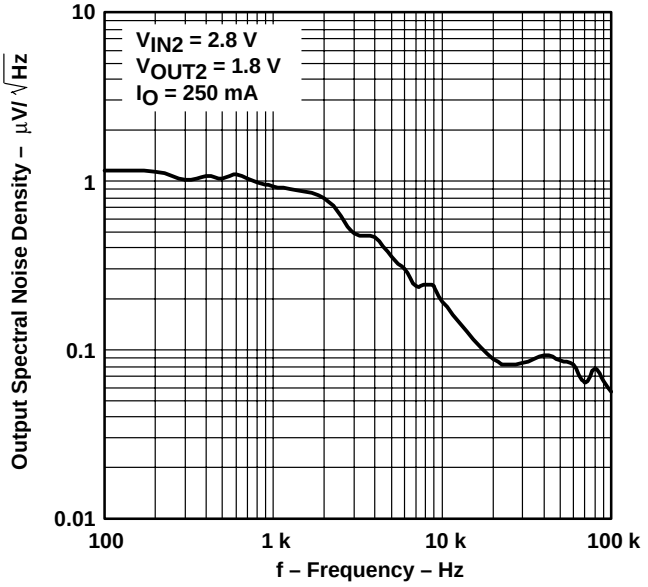


Figure 16

TYPICAL CHARACTERISTICS

OUTPUT IMPEDANCE vs FREQUENCY

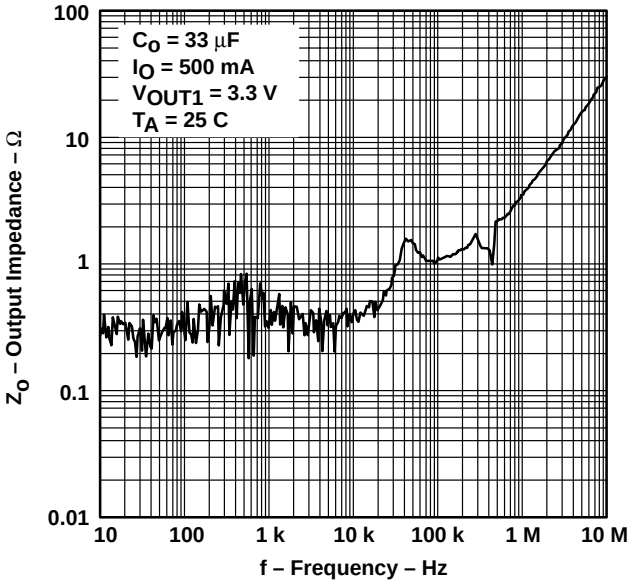


Figure 17

OUTPUT IMPEDANCE vs FREQUENCY

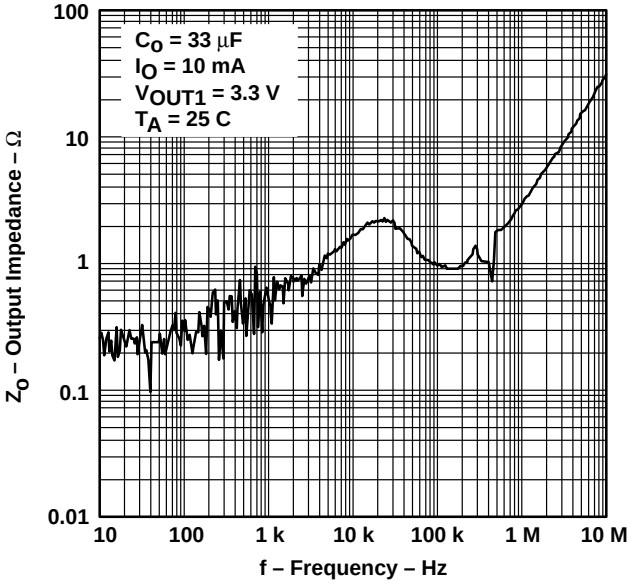


Figure 18

OUTPUT IMPEDANCE vs FREQUENCY

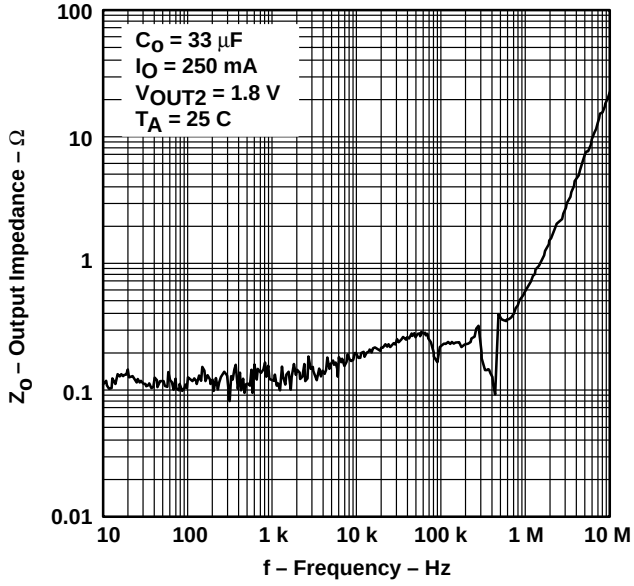


Figure 19

OUTPUT IMPEDANCE vs FREQUENCY

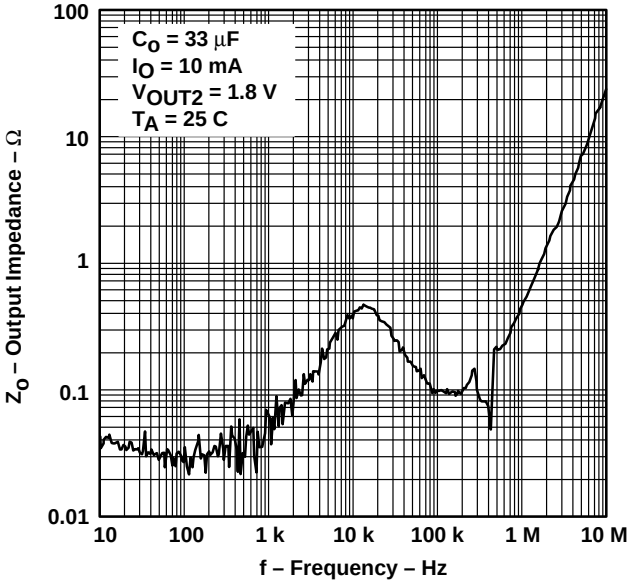


Figure 20

TYPICAL CHARACTERISTICS

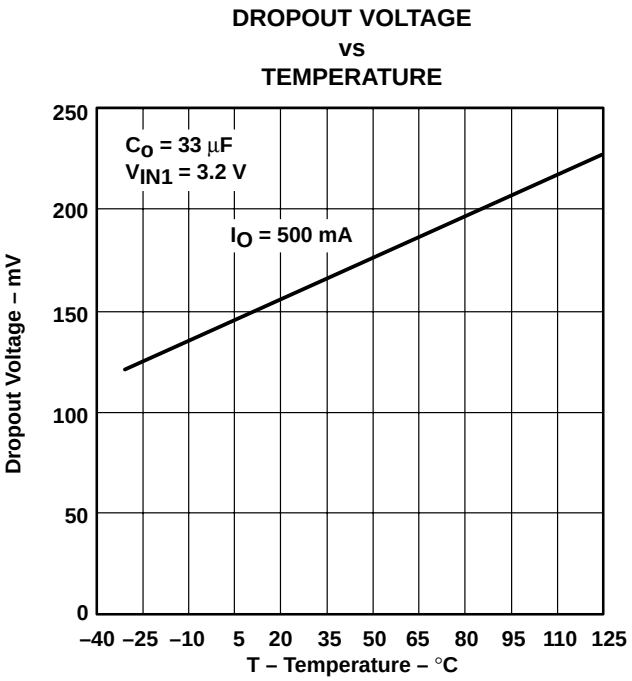


Figure 21

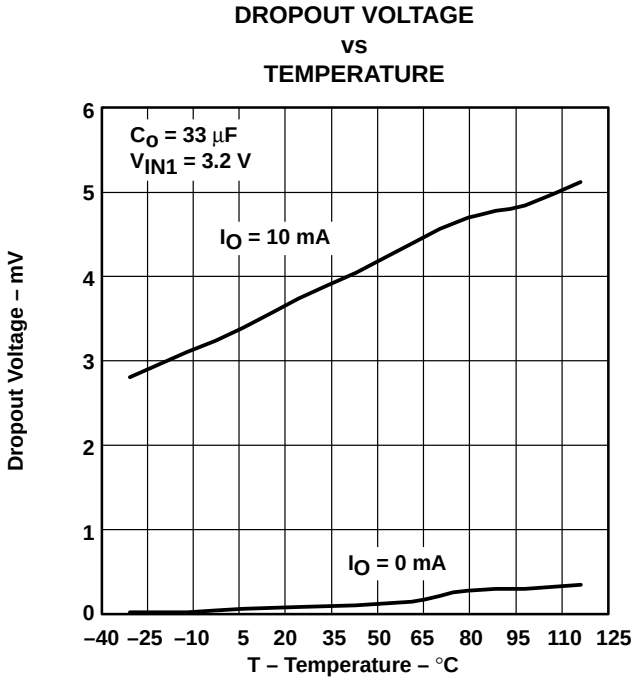


Figure 22

5V的输入，回差电压比较小。

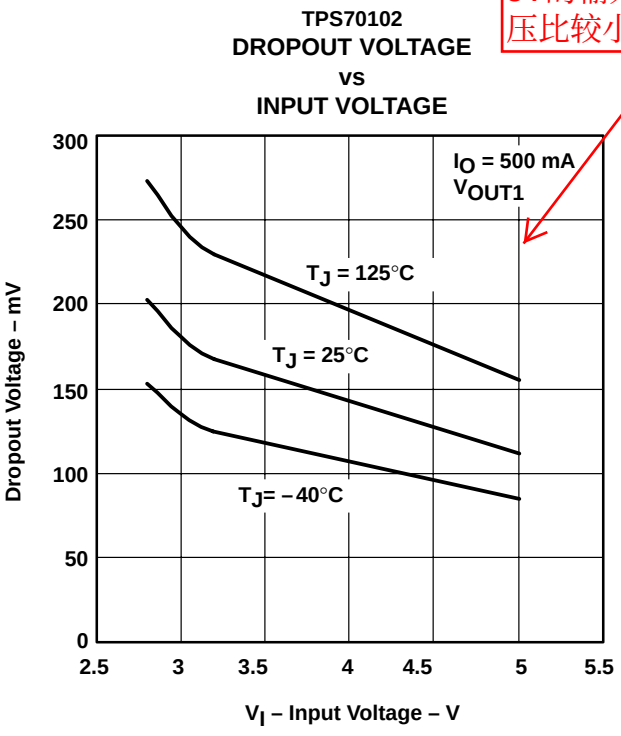


Figure 23

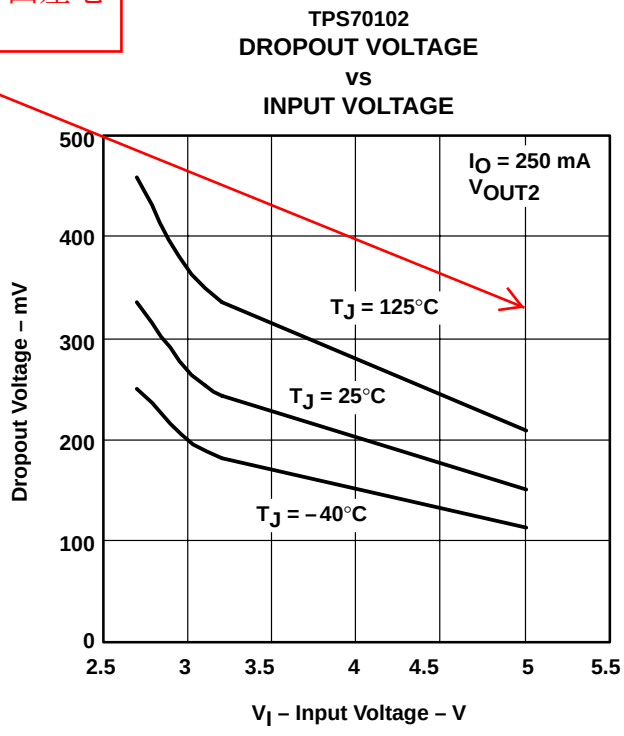


Figure 24

TYPICAL CHARACTERISTICS

LOAD TRANSIENT RESPONSE

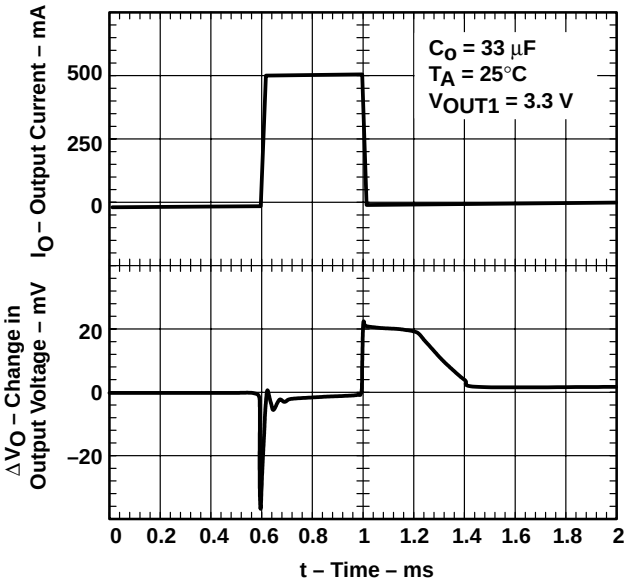


Figure 25

LOAD TRANSIENT RESPONSE

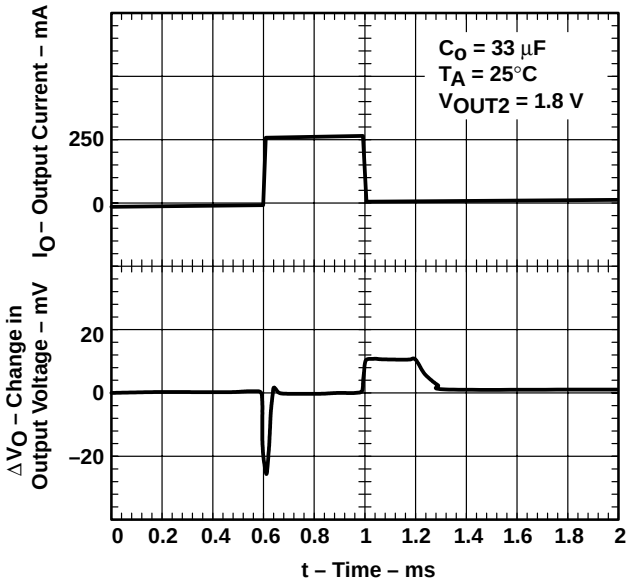


Figure 26

LINE TRANSIENT RESPONSE

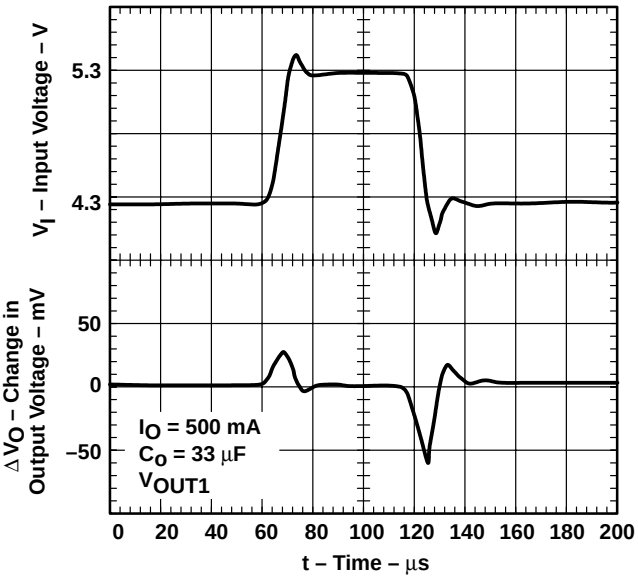


Figure 27

LINE TRANSIENT RESPONSE

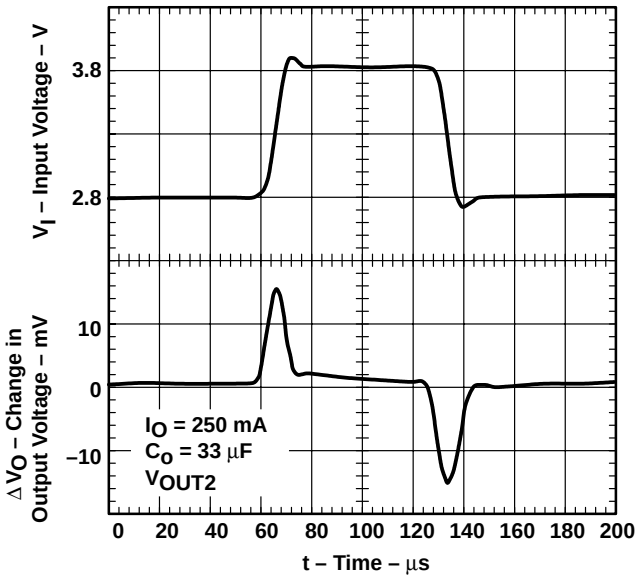


Figure 28

使能后，输出的响应时间，大约是0.4ms。

TYPICAL CHARACTERISTICS

OUTPUT VOLTAGE AND ENABLE VOLTAGE vs TIME (START-UP)

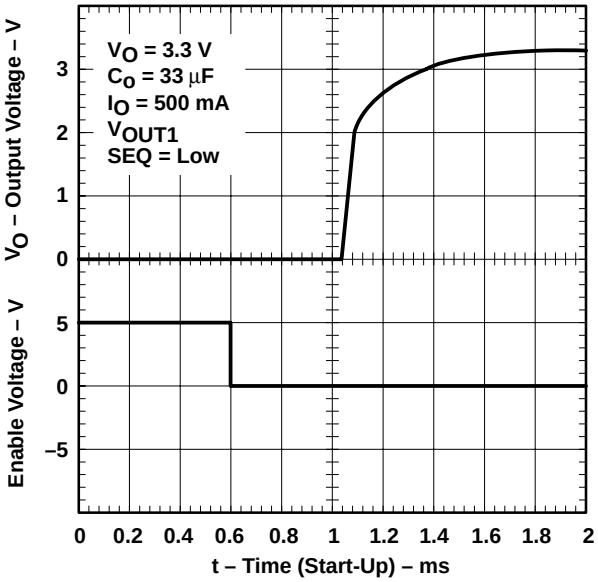


Figure 29

OUTPUT VOLTAGE AND ENABLE VOLTAGE vs TIME (START-UP)

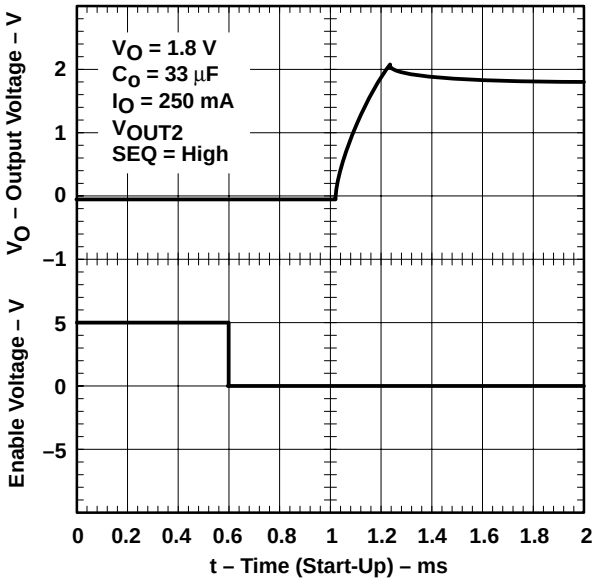


Figure 30

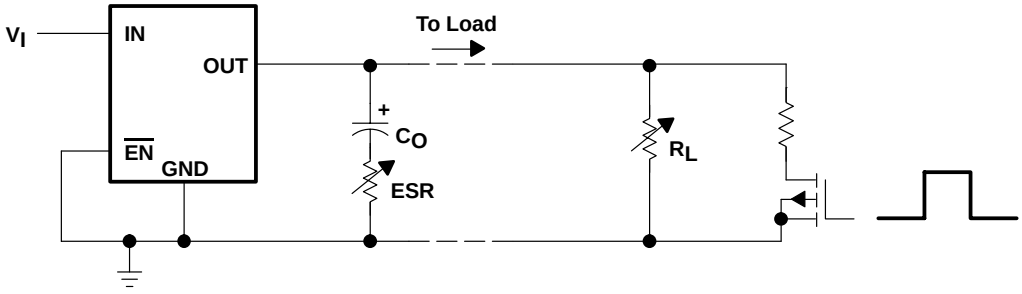


Figure 31. Test Circuit for Typical Regions of Stability

† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

TYPICAL CHARACTERISTICS

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

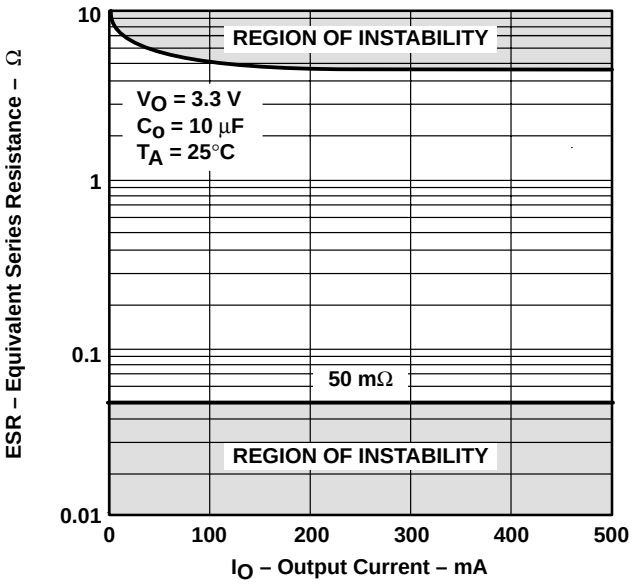


Figure 32

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

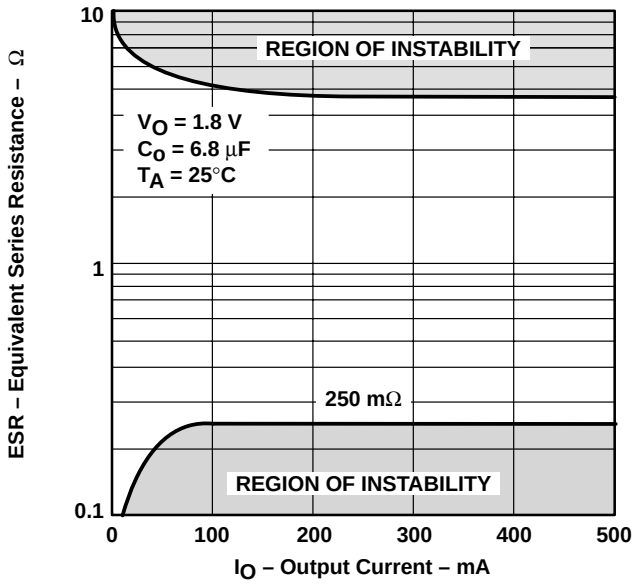


Figure 33

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

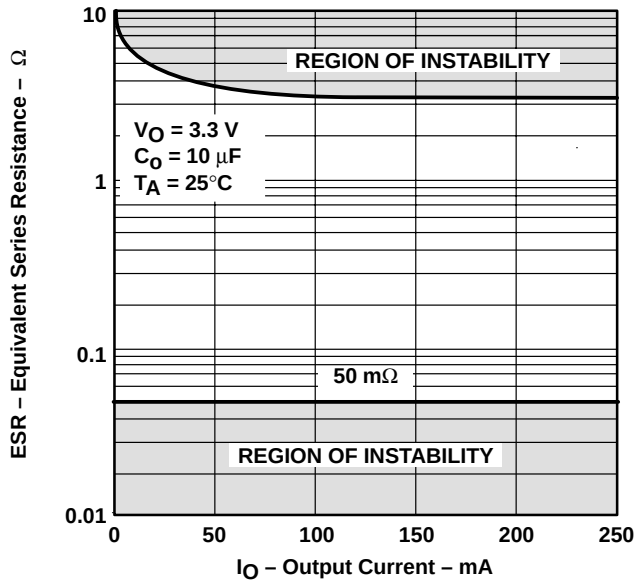


Figure 34

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

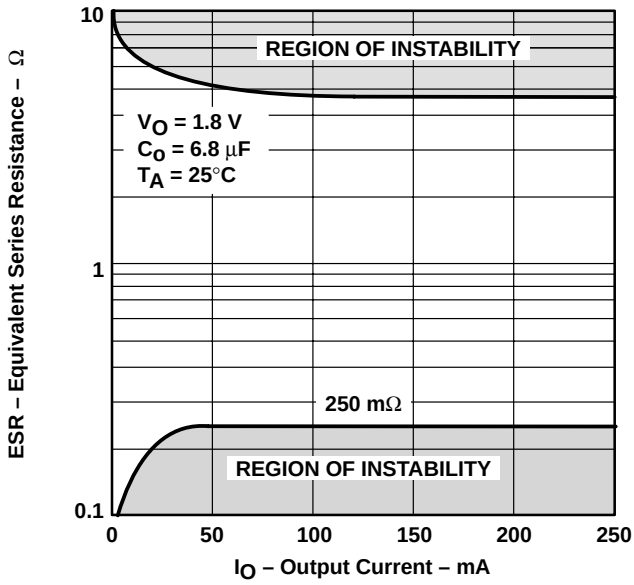


Figure 35

† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

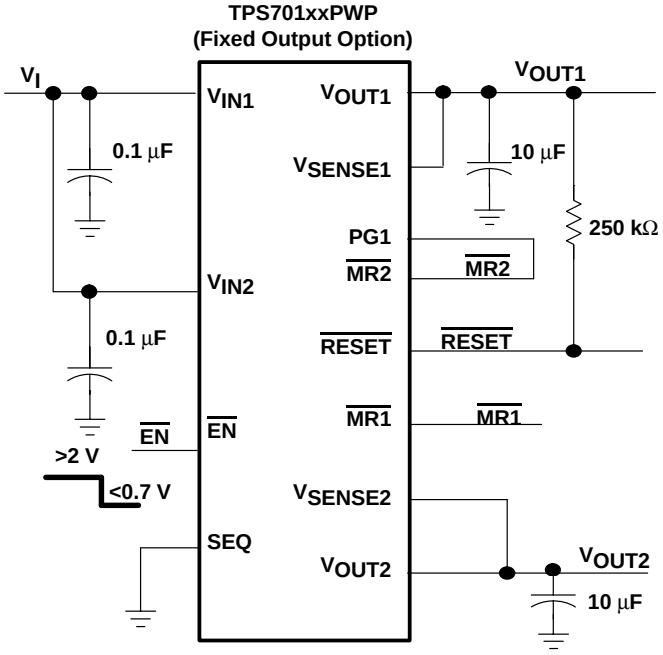
APPLICATION INFORMATION

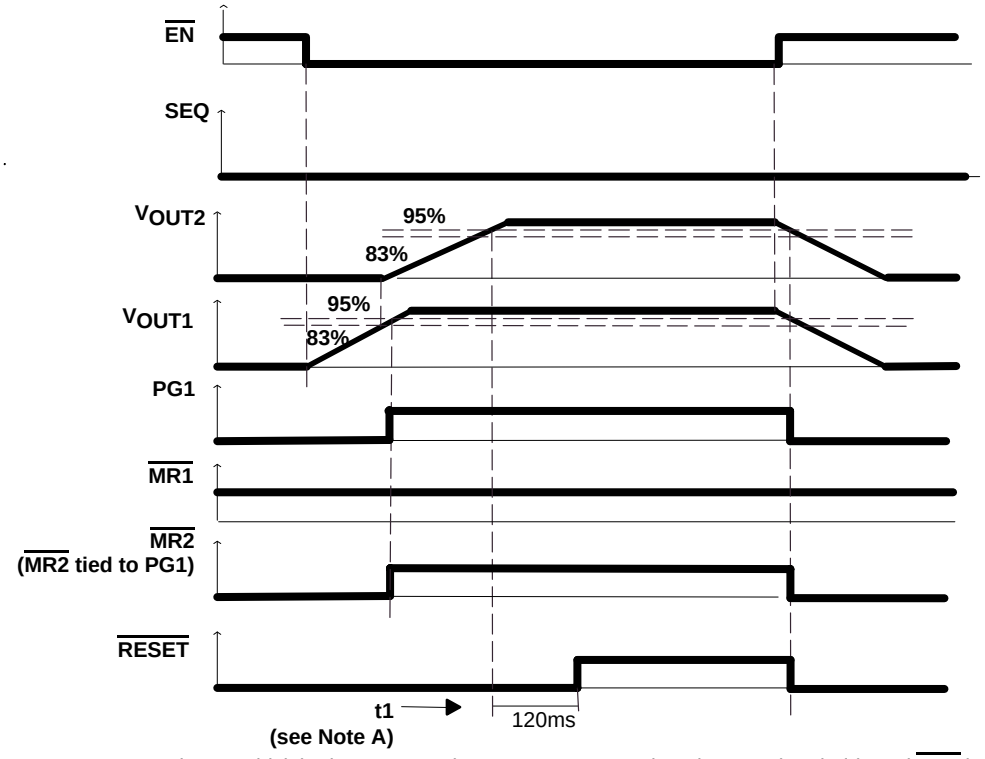
sequencing timing diagrams

The following figures provide a timing diagram of how this device functions in different configurations.

Application condition: $\overline{MR2}$ is tied to PG1, V_{IN1} and V_{IN2} are tied to same input voltage, the SEQ pin is tied to logic low and the device is toggled with enable ($\overline{EN}$) function.

When the device is enabled ($\overline{EN}$ is pulled low), V_{OUT1} turns on first and V_{OUT2} remains off until V_{OUT1} reaches approximately 83% of its regulated output voltage. At that time, V_{OUT2} is turned on. When V_{OUT1} reaches 95% of its regulated output, PG1 turns on (active high). Since $\overline{MR2}$ is connected to PG1 for this application, it follows PG1. When V_{OUT2} reaches 95% of its regulated voltage, $\overline{RESET}$ switches to high voltage level after 120 ms delay (see Figure 36).





NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

Figure 36. Timing When SEQ = Low

APPLICATION INFORMATION

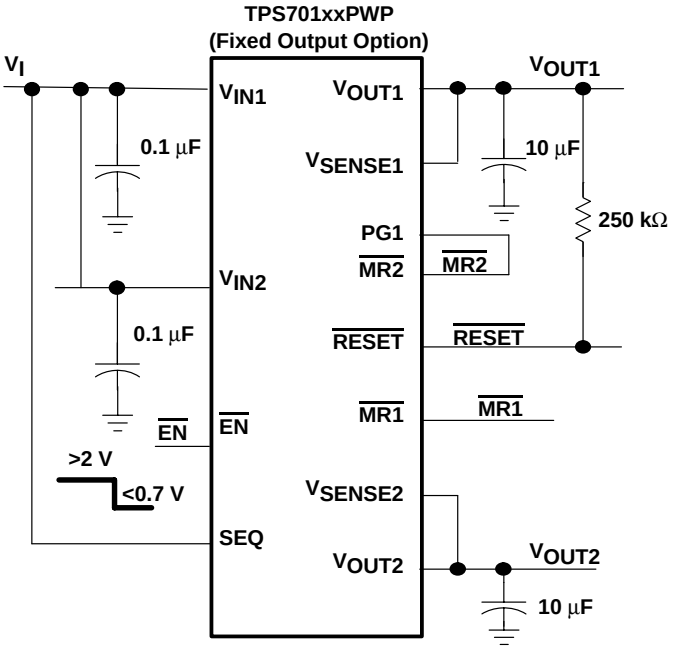
用于监视VOUT1

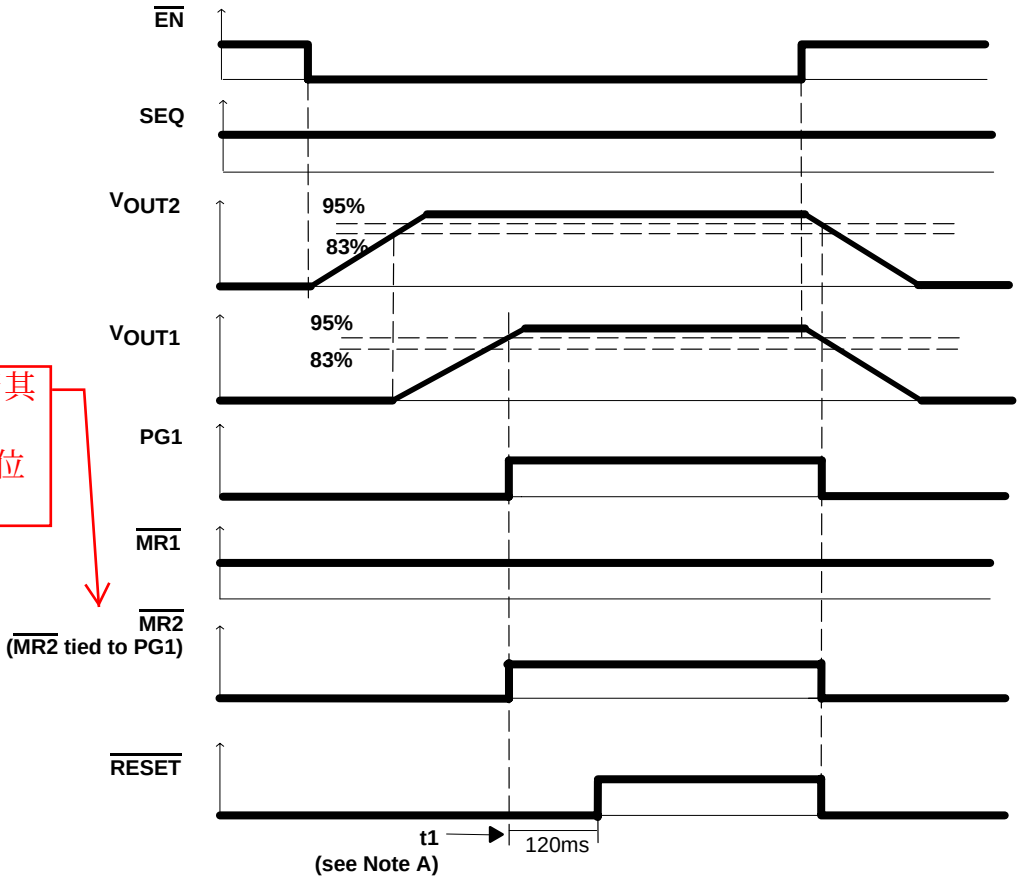
sequencing timing diagrams (continued)

Application condition: $\overline{MR2}$ is tied to PG1, V_{IN1} and V_{IN2} are tied to same input voltage, the SEQ pin is tied to logic high and the device is toggled with enable ($\overline{EN}$) function.

SEQ为高电平，则先给VOUT2上电。

When the device is enabled ($\overline{EN}$ is pulled low), V_{OUT2} begins to power up and when it reaches 83% of its regulated voltage, V_{OUT1} begins to power up. PG1 turns on when V_{OUT1} reaches 95% of its regulated voltage, and since $\overline{MR2}$ and PG1 are tied together, $\overline{MR2}$ follows PG1. When V_{OUT1} reaches 95% of its regulated voltage, $\overline{RESET}$ switches to high voltage level after 120 ms delay (see Figure 37).





监视VOUT1，当其低于额定输出的95%时，产生复位信号。

NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

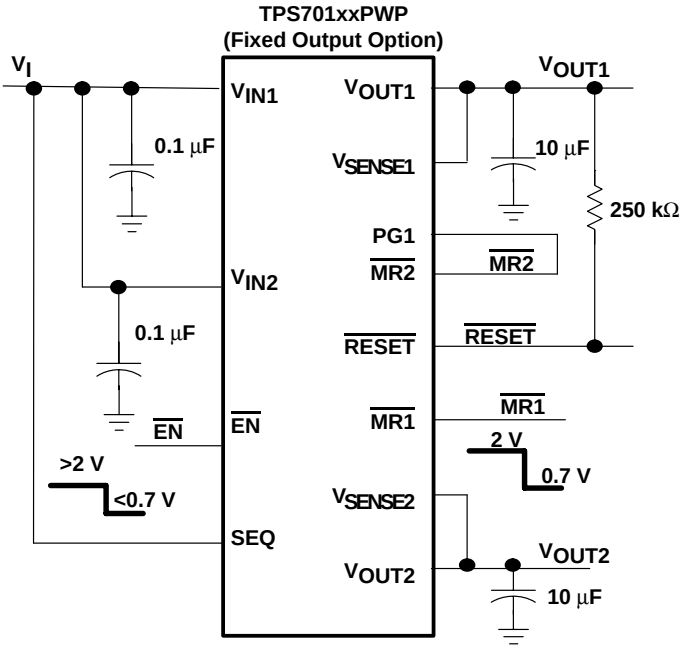
Figure 37. Timing When SEQ = High

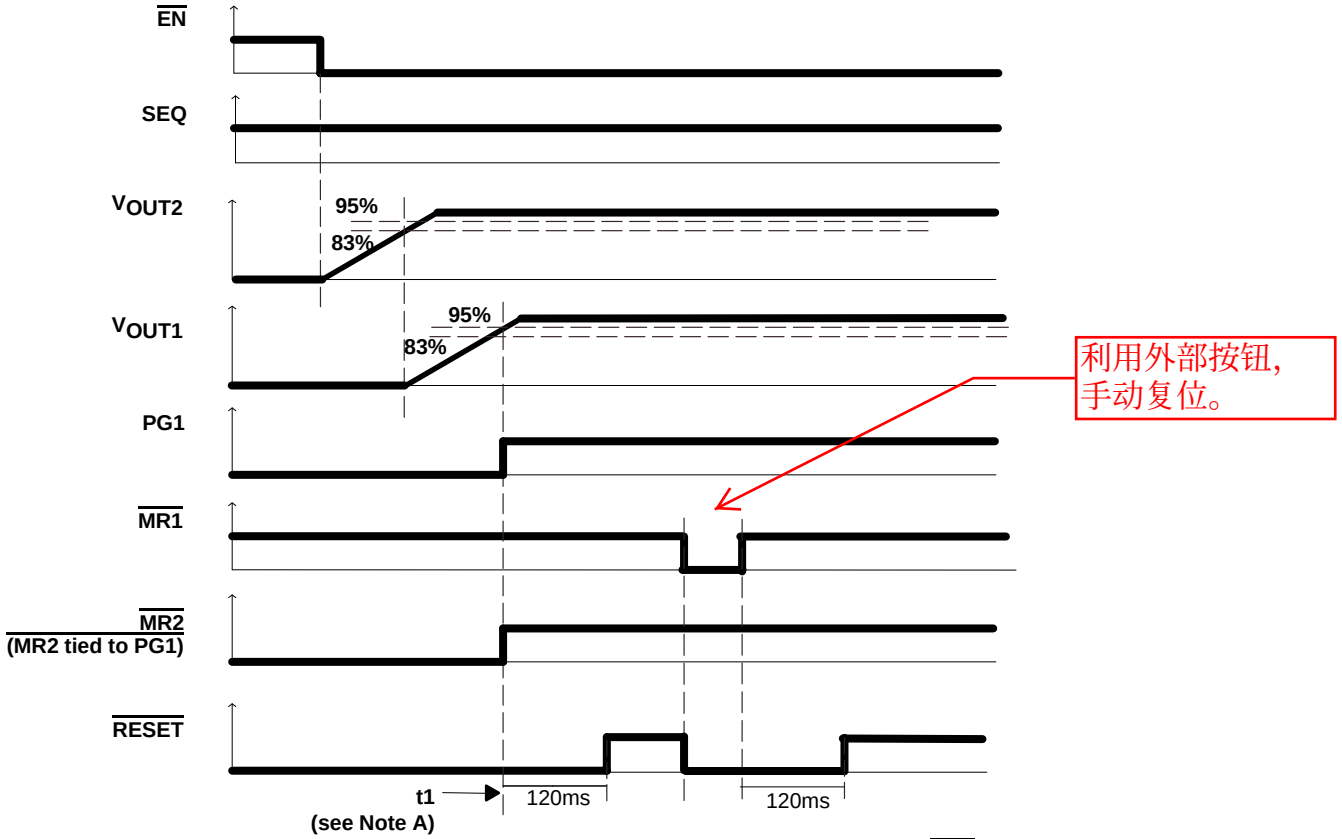
APPLICATION INFORMATION

sequencing timing diagrams (continued)

Application condition: $\overline{MR2}$ is tied to PG1, V_{IN1} and V_{IN2} are tied to same input voltage, the SEQ pin is tied to logic high and $\overline{MR1}$ is toggled.

When the device is enabled ($\overline{EN}$ is pulled low), V_{OUT2} begins to power up and when it reaches 83% of its regulated voltage, V_{OUT1} begins to power up. PG1 turns on when V_{OUT1} reaches to 95% of its regulated voltage, and since the $\overline{MR2}$ and PG1 are tied together, $\overline{MR2}$ follows PG1. When V_{OUT1} reaches to 95% of its regulated voltage, the $\overline{RESET}$ switches to high voltage level after 120 ms delay. When $\overline{MR1}$ is pulled low, it causes $\overline{RESET}$ to go low but the regulators remains in regulation. (see Figure 38)





NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

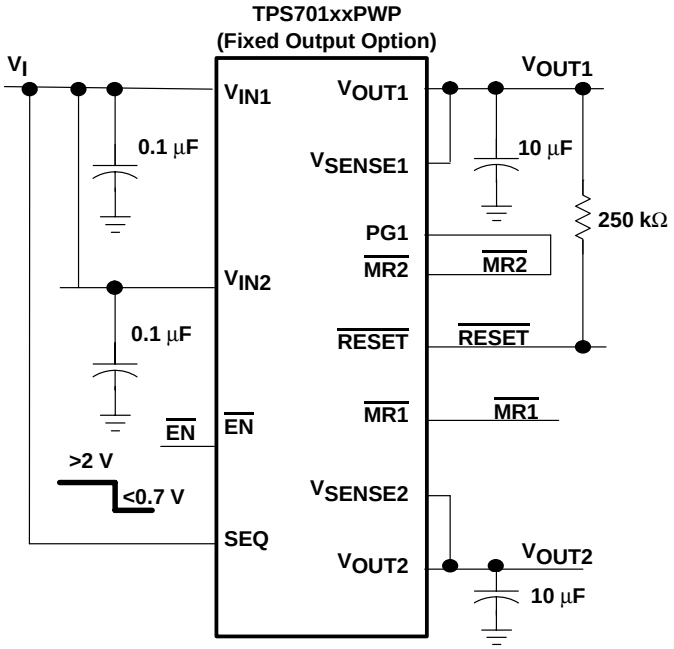
Figure 38. Timing When $\overline{MR1}$ is Toggled

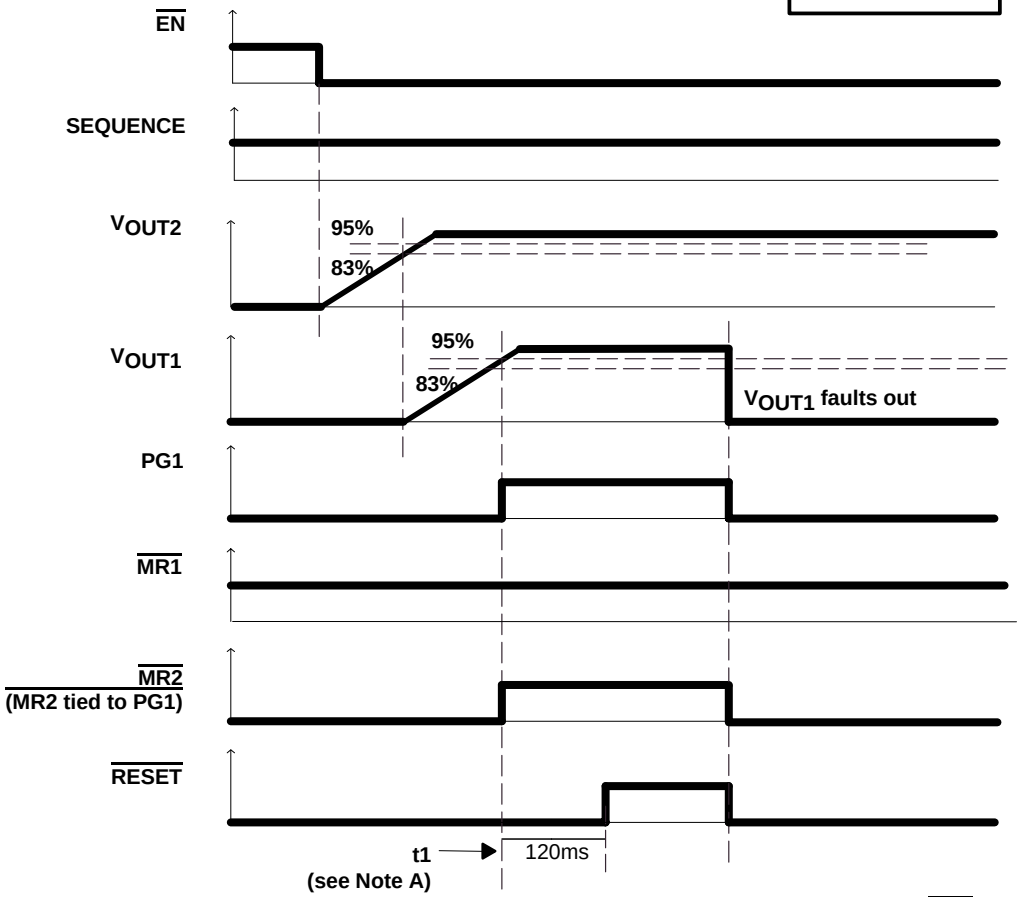
APPLICATION INFORMATION

sequencing timing diagrams (continued)

Application condition: $\overline{MR2}$ is tied to PG1, V_{IN1} and V_{IN2} are tied to same input voltage, the SEQ pin is tied to logic high and V_{OUT1} faults out.

V_{OUT2} begins to power up when device is enabled ($\overline{EN}$ is pulled low). When V_{OUT2} reaches 83% of its regulated voltage, then V_{OUT1} begins to power up. When V_{OUT1} reaches 95% of its regulated voltage, the PG1 turns on and $\overline{RESET}$ switches to high voltage level after 120 ms delay. When V_{OUT1} faults out, V_{OUT2} remains powered on because SEQ is high. PG1 is tied to $\overline{MR2}$ and both change state to logic low. $\overline{RESET}$ is driven by $\overline{MR2}$ and goes to logic low when V_{OUT1} faults out (see Figure 39).





NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

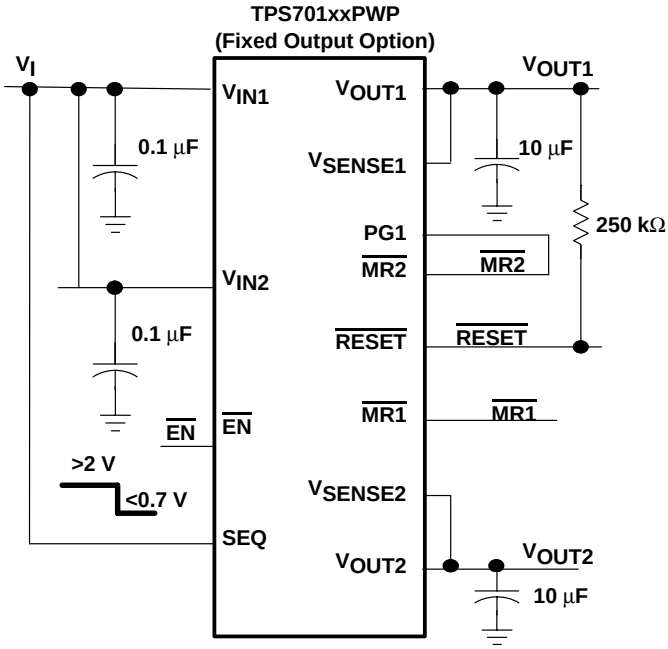
Figure 39. Timing When V_{OUT1} Faults Out

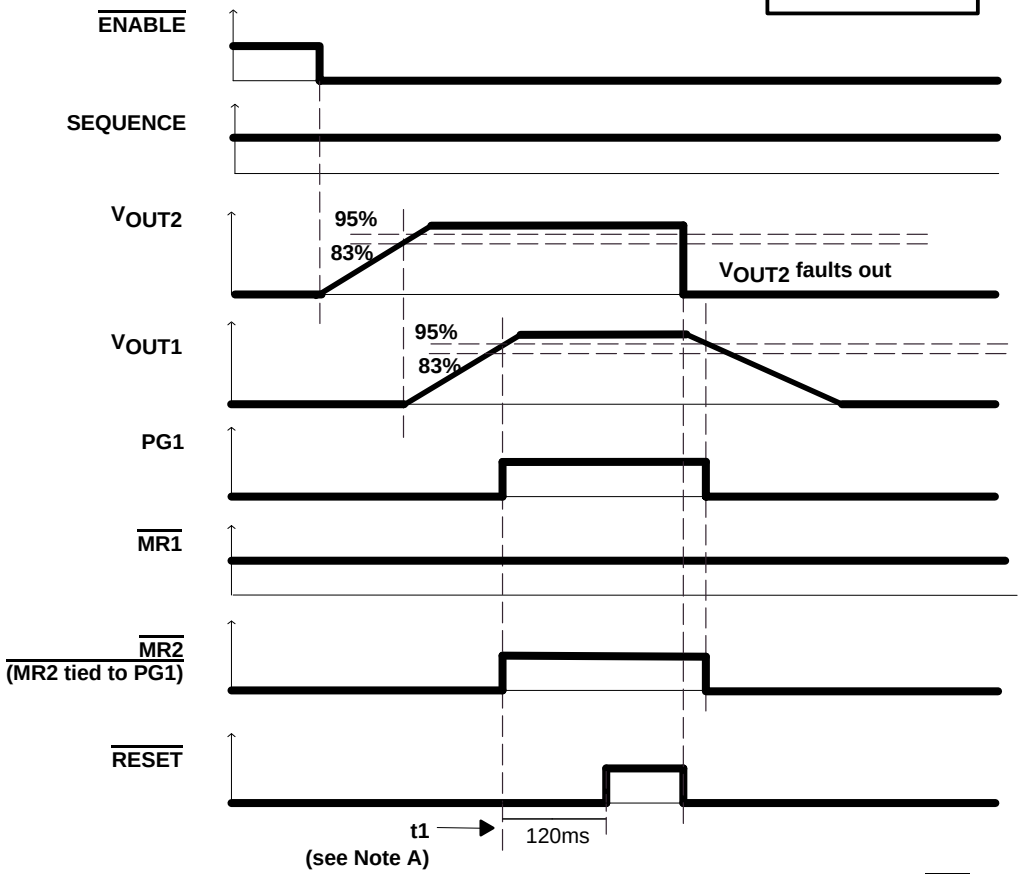
APPLICATION INFORMATION

sequencing timing diagrams (continued)

Application condition: $\overline{MR2}$ is tied to PG1, V_{IN1} and V_{IN2} are tied to same input voltage, the SEQ is tied to logic high, device is enabled, and V_{OUT2} faults out.

V_{OUT2} begins to power up when device is enabled ($\overline{EN}$ is pulled low). When V_{OUT2} reaches 83% of its regulated voltage, V_{OUT1} begins to power up. When V_{OUT1} reaches 95% of its regulated voltage, PG1 turns on and $\overline{RESET}$ switches to high voltage level after 120 ms delay. When V_{OUT2} faults out, V_{OUT1} is powered down because SEQ is high. PG1 is tied to $\overline{MR2}$ and both change state to logic low. $\overline{RESET}$ goes low when V_{OUT2} faults out (see Figure 40).





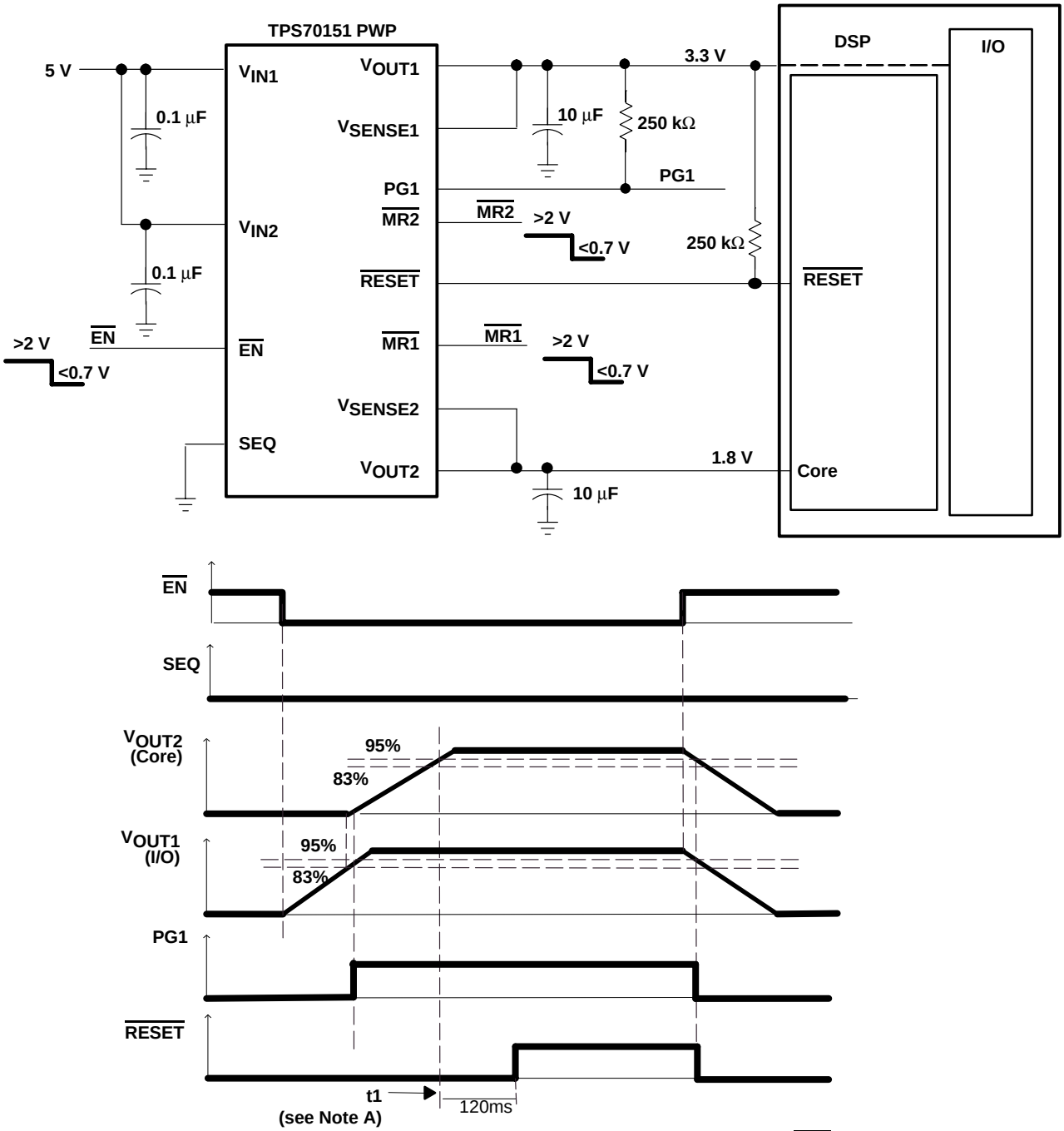
NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

Figure 40. Timing When V_{OUT2} Faults Out

APPLICATION INFORMATION

split voltage DSP application

Figure 41 shows a typical application where the TPS70151 is powering up a DSP. In this application, by grounding the SEQ pin, V_{OUT1}(I/O) is powered up first, and then V_{OUT2}(core).



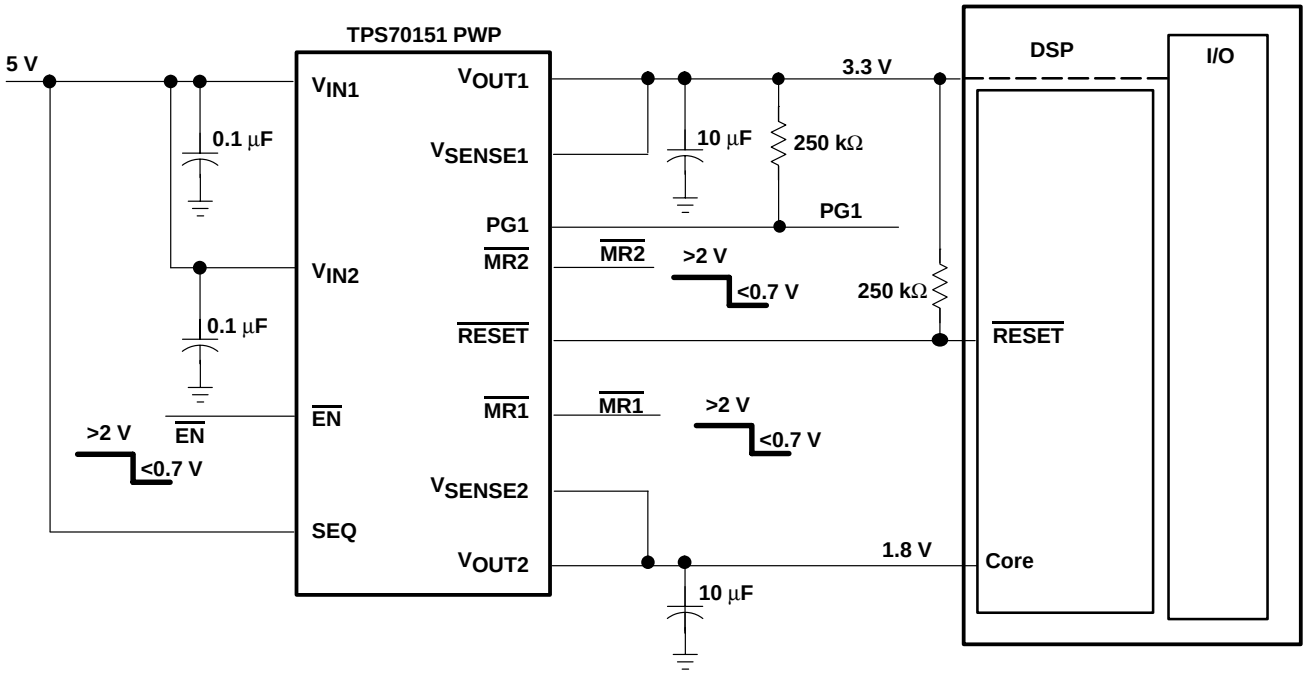
NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

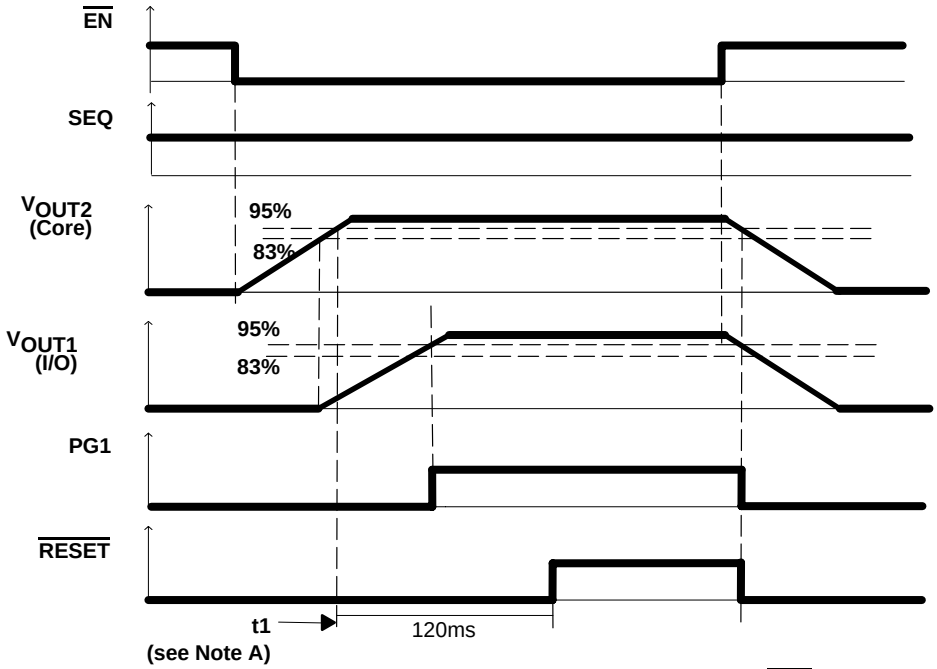
Figure 41. Application Timing Diagram (SEQ = Low)

APPLICATION INFORMATION

split voltage DSP application (continued)

Figure 42 shows a typical application where the TPS70151 is powering up a DSP. In this application, by pulling up the SEQ pin, V_{OUT2}(Core) is powered up first, and then V_{OUT1}(I/O).





NOTE A: t1 – Time at which both V_{OUT1} and V_{OUT2} are greater than the PG1 thresholds and $\overline{MR1}$ is logic high.

Figure 42. Application Timing Diagram (SEQ = High)

APPLICATION INFORMATION

input capacitor

For a typical application, an input bypass capacitor (0.1 µF – 1 µF) is recommended. This capacitor filters any high frequency noise generated in the line. For fast transient condition where droop at the input of the LDO may occur due to high inrush current, it is recommended to place a larger capacitor at the input as well. The size of this capacitor is dependant on the output current and response time of the main power supply, as well as the distance to the V_I pins of the LDO.

output capacitor

As with most LDO regulators, the TPS701xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 µF and the ESR (equivalent series resistance) must be between 50 mΩ and 2.5 Ω. Capacitor values 10 µF or larger are acceptable, provided the ESR is less than 2.5 Ω. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Larger capacitors provide a wider range of stability and better load transient response. Below is a partial listing of surface-mount capacitors usable with the TPS701xx for fast transient response application.

This information, along with the ESR graphs, is included to assist in selection of suitable capacitance for the user's application. When necessary to achieve low height requirements along with high output current and/or high load capacitance, several higher ESR capacitors can be used in parallel to meet the guidelines above.

VALUE	MFR.	MAX ESR	PART NO.
22 µF	Kemet	345 mΩ	7495C226K0010AS
33 µF	Sanyo	100 mΩ	10TPA33M
47 µF	Sanyo	100 mΩ	6TPA47M
68 µF	Sanyo	45 mΩ	10TPC68M

ESR and transient response

LDOs typically require an external output capacitor for stability. In fast transient response applications, capacitors are used to support the load current while LDO amplifier is responding. In most applications, one capacitor is used to support both functions.

Besides its capacitance, every capacitor also contains parasitic impedances. These parasitic impedances are resistive as well as inductive. The resistive impedance is called equivalent series resistance (ESR), and the inductive impedance is called equivalent series inductance (ESL). The equivalent schematic diagram of any capacitor can therefore be drawn as shown in Figure 43.

Figure 43. – ESR and ESL

In most cases one can neglect the effect of inductive impedance ESL. Therefore, the following application focuses mainly on the parasitic resistance ESR.

APPLICATION INFORMATION

Figure 44 shows the output capacitor and its parasitic impedances in a typical LDO output stage.

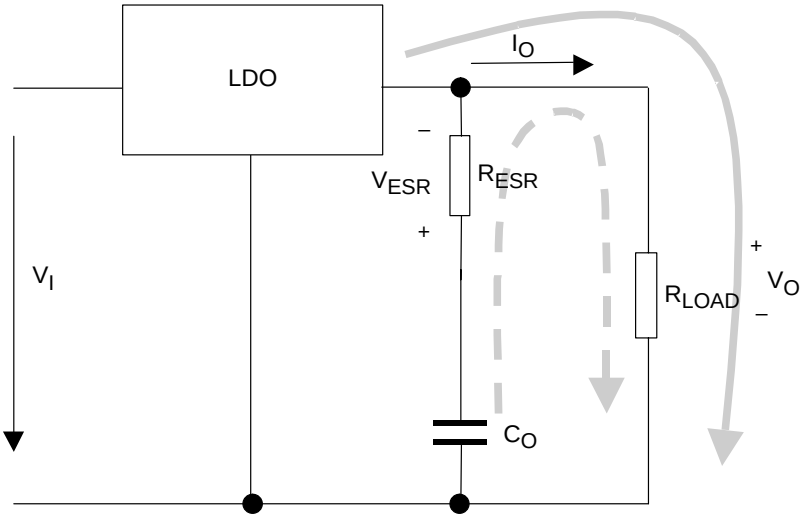


Figure 44. – LDO Output Stage With Parasitic Resistances ESR

In steady state (dc state condition), the load current is supplied by the LDO (solid arrow) and the voltage across the capacitor is the same as the output voltage ($V(C_O) = V_O$). This means no current is flowing into the C_O branch. If I_O suddenly increases (transient condition), the following occurs:

- The LDO is not able to supply the sudden current need due to its response time (t_1 in Figure 45). Therefore, capacitor C_O provides the current for the new load condition (dashed arrow). C_O now acts like a battery with an internal resistance, ESR. Depending on the current demand at the output, a voltage drop occurs at R_{ESR}. This voltage is shown as V_{ESR} in Figure 44.
- When C_O is conducting current to the load, initial voltage at the load will be $V_O = V(C_O) – V_{ESR}$. Due to the discharge of C_O, the output voltage V_O drops continuously until the response time t_1 of the LDO is reached and the LDO resumes supplying the load. From this point, the output voltage starts rising again until it reaches the regulated voltage. This period is shown as t_2 in Figure 45.

The figure also shows the impact of different ESRs on the output voltage. The left brackets show different levels of ESRs where number 1 displays the lowest and number 3 displays the highest ESR.

From above, the following conclusions can be drawn:

- The higher the ESR, the larger the droop at the beginning of load transient.
- The smaller the output capacitor, the faster the discharge time and the bigger the voltage droop during the LDO response period.

APPLICATION INFORMATION

conclusion

To minimize the transient output droop, capacitors must have a low ESR and be large enough to support the minimum output voltage requirement.

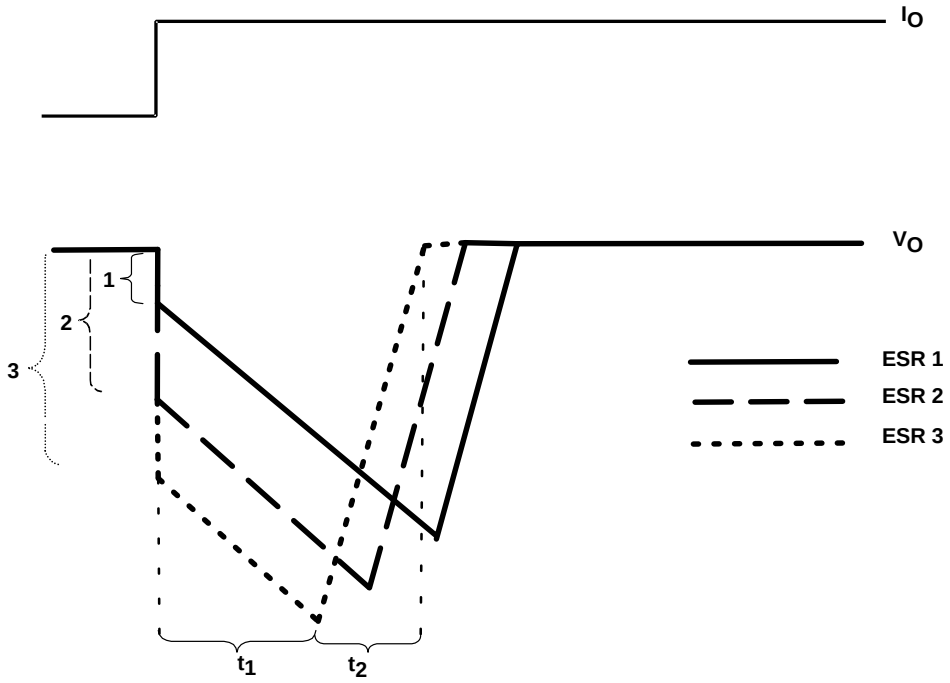


Figure 45. – Correlation of Different ESRs and Their Influence to the Regulation of V_O at a Load Step From Low-to-High Output Current

APPLICATION INFORMATION

programming the TPS70102 adjustable LDO regulator

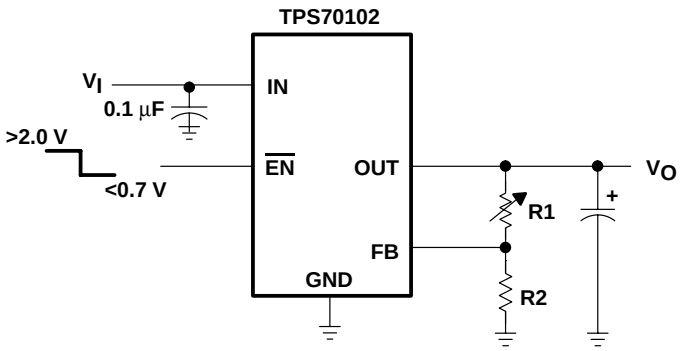
The output voltage of the TPS70102 adjustable regulators are programmed using external resistor dividers as shown in Figure 46.

Resistors R1 and R2 should be chosen for approximately 50 μA divider current. Lower value resistors can be used, but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at the sense terminal increase the output voltage error. The recommended design procedure is to choose R2 = 30.1 kΩ to set the divider current at approximately 50 μA and then calculate R1 using:

$$R1 = \left(\frac{V_O}{V_{ref}} - 1\right) \times R2$$

where

V_{ref} = 1.224 V typ (the internal reference voltage)



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	31.6	30.1	kΩ
3.3 V	51.1	30.1	kΩ
3.6 V	59.0	30.1	kΩ

Figure 46. TPS70102 Adjustable LDO Regulator Programming

regulator protection

Both TPS701xx PMOS-pass transistors have built-in back diodes that conduct reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS701xx also features internal current limiting and thermal protection. During normal operation, the TPS701xx regulator 1 limits output current to approximately 1.6 A (typ) and regulator 2 limits output current to approximately 750 mA (typ). When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

APPLICATION INFORMATION

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_D, which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

where

$T_J max$ is the maximum allowable junction temperature.

$R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 32.6°C/W for the 20-terminal PWP with no airflow.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

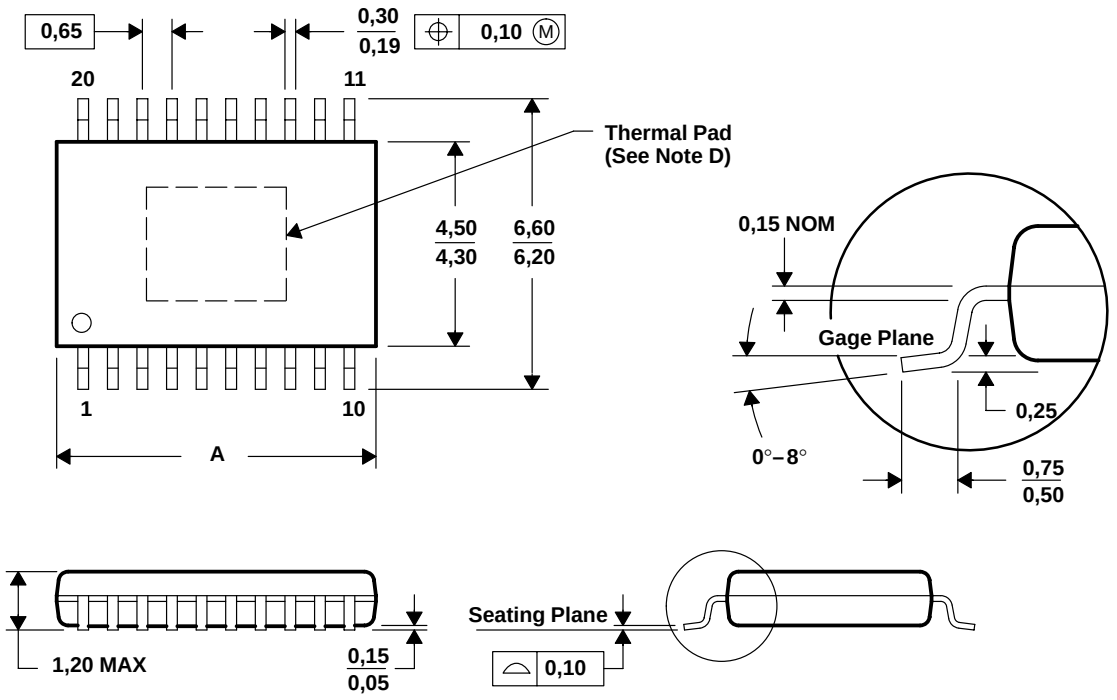
$$P_D = \left(V_I - V_O\right) \times I_O$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

MECHANICAL DATA

PWP (R-PDSO-G)** **PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE**

20-PIN SHOWN



DIM \ PINS **	14	16	20	24	28
A MAX	5,10	5,10	6,60	7,90	9,80
A MIN	4,90	4,90	6,40	7,70	9,60

4073225/E 03/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions.
D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
E. Falls within JEDEC MO-153

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